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GENERAL INFORMATION

Many Microchip products are available packed into embossed tape that is wound onto a reel. This document provides the general specifications for such packing.

This specification follows the Electronic Components Industry Association standard EIA-481.

Material from EIA-481-E is used with permission of the Electronic Components Industry Association. This standard is available for purchase from IHS (www.global.ihs.com).

EMBOSSED TAPE DIMENSIONS

Embossed tape 8 mm through 24 mm wide has a single row of sprocket holes along one edge of the tape, as shown in Figure 1.

- · Constant dimensions are listed in Table 1.
- Variable dimensions, except for the individual cavity dimensions, are listed in Table 2.
- Cavity dimensions are listed in Table 5 through Table 13.

Embossed tape 32 mm through 200 mm wide has a single row of sprocket holes along both edges of the tape, as shown in Figure 2.

- Constant dimensions are listed in Table 3.
- Variable dimensions, except for the individual cavity dimensions, are listed in Table 4.
- Cavity dimensions are listed in Table 5 through Table 13.



FIGURE 1: 8, 12, 16 and 24 mm EMBOSSED CARRIER TAPE DIMENSIONS

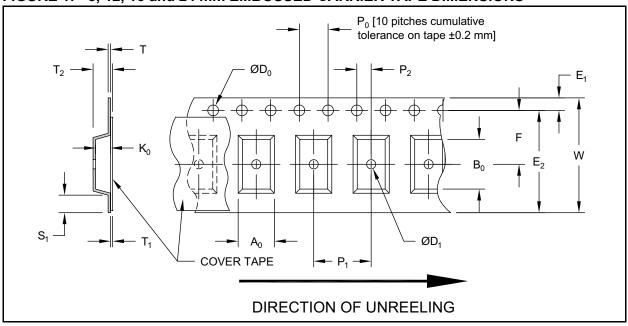


Table 1: Constant Dimensions for Embossed 8 mm~24 mm Carrier Tape

Tape Size	D ₀	D ₁ Min.	E ₁	P ₀	P ₂	R (Ref.)	S ₁ Min.	T Max.	T ₁ Max
8 mm		1.0			2.0±0.05	25			
12 mm	1 = +0.1	1.5	1.75±0.1	4.0±0.1	2.0±0.05	30	0.6	0.6	0.1
16 mm	1.5 ^{+0.1} _{-0.0}	1.5	1.75±0.1	4.0±0.1	2.0±0.1	30	0.0	0.6	0.1
24 mm		1.5			2.0±0.1	30			

Table 2: Variable Dimensions for Embossed 8 mm~24 mm Carrier Tape

Tape Size	B ₁ Max.	E ₂ Max.	F	P ₁	T ₂ Max.	W Max.	A ₀ , B ₀ , & K ₀
8 mm	4.35	6.25	3.5±0.05	2.0±0.5 or 4.0±0.1	2.5	8.3	
12 mm	8.2	10.25	5.5±0.05	2.0±0.05 or 4.0±0.1 or 8.0±0.1	6.5	12.3	See Table 5
16 mm	12.1	14.25	7.5±0.1	4.0±0.05 to 12.0±0.1 in 4.0 increments	8.0	16.3	through Table 13
24 mm	20.1	22.25	11.5±0.1	4.0±0.05 to 20.0±0.1 in 4.0 increments	12.0	24.3	



FIGURE 2: 32, 44, 56, 72, 88, 104, 120, 136, 152, 168, 184 and 200 mm EMBOSSED CARRIER DIMENSIONS

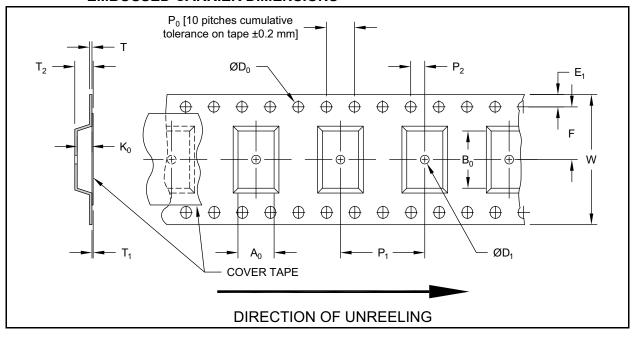


Table 3: Constant Dimensions for Embossed 32 mm to 200 mm Carrier Tape

Tape Size	D ₀	D ₁ Min.	E ₁	P ₀	P ₂	R (Ref.)	T Max.	T ₁ Max
32 mm					2.0±0.1	50		
44 mm	1.5 ^{+0.1} _{-0.0}	2.0	1.75±0.1	4.0±0.1	2.0±0.15	30	0.6	0.1
56 mm	1.5 -0.0	2.0	1.7 J±0.1	4.0±0.1	2.0±0.2	75	0.0	0.1
72 through 200 mm					2.0±0.2	2		



Table 4: Variable Dimensions for Embossed 32 mm to 200 mm Carrier Tape

Tape Size	B ₁ Max.	F	P ₁ ±0.1	S ₀ ±0.1	T ₂ Max.	W Max. ±0.3	A ₀ , B ₀ , & K ₀
32	23.0	14.2±0.10	4.0 to 32.0	28.4	12.0	32.0	
44	35.0	20.2±0.15	4.0 to 44.0	40.4	16.0	44.0	
56	46.0	26.2±0.15	4.0 to 56.0	52.4	20.0	56.0	
72	60.0	34.2±0.30		68.4	30.0	72.0	
188	76.0	42.2±0.30		84.4	30.0	88.0	
104	91.0	50.2±0.35		100.4	35.0	104.0	See Table 5
120	107.0	58.2±0.35		116.4	40.0	120.0	through Table 13
136	123.0	66.2±0.40	4.0 to 72.0	132.4	40.0	136.0	
152	139.0	74.2±0.40		148.4	40.0	152.0	
168	153.0	82.2±0.45		164.4	40.0	168.0	
184	169.0	90.2±0.45		180.4	40.0	184.0	
200	185.0	98.2±0.50		196.4	40.0	200.0	



INDEX MARKING QUADRANTS

Most devices have an index marking on the top surface, indicating the location of terminal 1 or A1, as appropriate. The location of the index within the cavity is indicated by dividing the cavity into numbered quadrants, and listing the quadrant in which the index mark appears.

FIGURE 3: Index Marking Quadrants

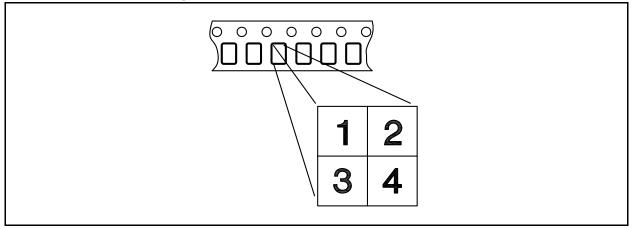
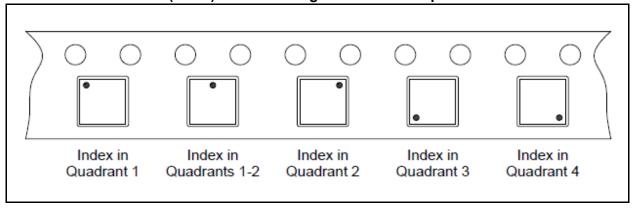


FIGURE 4: Terminal 1 (or A1) Index Marking Quadrant Examples





EMBOSSED TAPE DIMENSION TABLES

The following tables list carrier tape and cavity dimensions by package type. The tables are organized according to the following criteria:

- Table 5 Plastic Products with Leads
- Table 6 No-Lead Plastic Products (DFN, QFN, SON, etc.)
- Table 7 Grid Array Products (LGA, BGA, etc.)
- Table 8 Modules
- Table 9 SMSC Automotive (AIS) Products
- Table 10 SMSC Commercial Products
- Table 11 Supertex Products
- Table 12 ISSC Products
- Table 13 Micrel Products



Table 5: Microchip Technology Plastic Products, with Leads, Carrier Tape and Cavity Dimensions

	Jimensions	Ī	I -						
Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity I	Dimensio	ns (mm)	Index Quadrant	
		Je O	W	P ₁	A ₀	B ₀	K ₀	_ §	
DDPAK		3	24	16	10.6	15.8	4.9	2	
DDPAK		5	24	16	10.6	15.8	4.9	2	
DDPAK		7	24	16	10.6	15.8	4.9	2	
DPAK		3	16	8	N/A	N/A	N/A	2	
LQFP	20x20x1.4 mm	144	44	32	23.5	23.5	2	2	
LQFP	20x20x1.4 mm	144	44	32	22.63	22.63	2.2	2	
MQFP	10x10x2 mm	44	24	24	14.2	14.2	2.8	2	
MQFP	14x14x2.7 mm	64	32	24	18	18	3.6	2	
MSOP	3x3x1.0 mm	8	12	8	5.3	3.4	1.4	1	
MSOP	3x3x1.0 mm	8	12	8	5.3	3.4	1.4	1	
MSOP	3x3x1.0 mm	10	12	8	5.3	3.4	1.4	1	
MSOP	3x3x1.0 mm	10	12	8	5.3	3.4	1.4	1	
PLCC	11.5x11.5x4.4 mm	28	24	16	13	13	4.9	1-2	
PLCC	11.5x11.5x4.4 mm	28	24	16	13	13	4.9	1-2	
PLCC	11.5x14x3.37 mm	32	24	16	13.1	15.5	3.9	1-2	
PLCC	16.6x16.6x4.4 mm	44	32	24	18	18	4.9	1-2	
PLCC	16.6x16.6x4.4 mm	44	32	24	18	18	4.9	1-2	
PLCC	24.2x24.2x44 mm	68	44	32	25.6	25.6	5.7	1-2	
PLCC	24.2x24.2x44 mm	68	44	32	25.6	25.6	5.8	1-2	
PLCC	24.2x24.2x44 mm	68	44	32	25.6	25.6	5.3	1-2	
PLCC	29.3x29.3x4.4 mm	84	44	36	30.7	30.7	5.8	1-2	
QSOP	3.90 mm (.150 inches)	16	12	8	6.4	5.2	2.1	2	
QSOP	3.90 mm (.150 inches)	16	12	8	6.4	5.2	2.1	2	
QSOP	3.90 mm (.150 inches)	16	12	8	6.23	5.4	2.12	2	
QSOP	3.90 mm (.150 inches)	16	12	8	6.5	5.2	2.1	2	
SC70		3	8	4	2.40	2.60	1.20	3	
SC70		5	8	4	2.25	2.40	1.22	2	
SC70		6	8	4	2.25	2.40	1.22	2	



Table 5: Microchip Technology Plastic Products, with Leads, Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity I	Dimensio	ns (mm)	Index Quadrant
		P O	w	P ₁	A ₀	B ₀	K ₀	_ §
SOIC	150 mils	8	12	8	6.4	5.2	2.1	1
SOIC	150 mils	8	12	8	6.5	5.2	2.1	1
SOIC	150 mils	8	12	8	6.4	5.2	2.1	1
SOIC	150 mils	8	12	8	6.4	5.2	2.1	1
SOIC	150 mils	8	12	8	6.4	5.2	2.1	1
SOIC	150 mils	14	16	8	6.5	9.5	2.1	1
SOIC	150 mils	14	16	8	6.4	9.05	2.1	1
SOIC	150 mils	14	16	8	6.55	9.5	2.1	1
SOIC	150 mils	16	16	8	6.5	10.3	2.1	1
SOIC	150 mils	16	16	8	6.5	10.3	2	1
SOIC	207 mils	8	16	12	8.3	5.7	2.3	1
SOIC	207 mils	8	16	12	8.4	7.7	2.5	1
SOIC	300 mils	16	16	12	10.9	10.7	3	1
SOIC	300 mils	18	24	16	11.1	12	2.8	1
SOIC	300 mils	18	24	16	11.05	12.04	2.84	1
SOIC	300 mils	18	24	16	11.1	12	2.8	1
SOIC	300 mils	18	24	12	10.9	13.3	3	1
SOIC	300 mils	20	24	12	10.9	13.3	3	1
SOIC	300 mils	24	24	12	10.9	16	3	1
SOIC	300 mils	28	24	12	10.9	18.5	3	1
SOIC	300 mils	28	24	12	10.9	18.5	3	1
SOIC	300 mils	28	24	12	10.9	18.5	3	1
SOP		8	12	8	N/A	N/A	N/A	1
SOT-143		4	8	4	3.19	2.8	1.31	3
SOT-223		3	12	8	6.83	7.42	1.88	3
SOT-223			12	8	6.83	7.42	1.88	3
SOT-23		3	8	4	3.15	2.77	1.22	3
SOT-23		3	8	4	3.15	2.77	1.22	3



Table 5: Microchip Technology Plastic Products, with Leads, Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity I	Dimensio	ns (mm)	Index Quadrant
		Te	W	P ₁	A ₀	B ₀	K ₀	_ ਕ
SOT-23		5	8	4	3.23	3.17	1.37	3
SOT-23		6	8	4	3.23	3.17	1.37	3
SOT-23A		3	8	4	3.25	3.15	1.55	3
SOT-89		3	12	8	4.7	4.5	1.7	3
SOT-89		3	12	8	4.8	4.4	1.8	3
SOT-89		5	12	8	N/A	N/A	N/A	3
SSOP	3.90 mm (.150 inches)	20	16	12	8.5	7.6	2.2	1
SSOP	3.90 mm (.150 inches)	20	16	12	8.4	7.6	2.5	1
SSOP	3.90 mm (.150 inches)	24	16	12	8.4	8.7	2.5	1
SSOP	3.90 mm (.150 inches)	28	24	12	8.3	10.7	2.2	1
SSOP	3.90 mm (.150 inches)	28	24	12	8.5	10.8	2.2	1
TO92		2	5	See Figure	13, Figur	e 14, and	Table 16	!
TO92		3	Ş	See Figure	13, Figur	e 14, and	Table 16	
TQFP	10x10x1.0 mm	44	24	16	12.45	12.45	1.6	2
TQFP	10x10x1.0 mm	44	24	16	12.4	12.4	1.6	2
TQFP	10x10x1.0 mm	64	24	16	12.45	12.45	1.6	2
TQFP	10x10x1.0 mm	64	24	16	12.4	12.4	1.6	2
TQFP	12x12x1.0 mm	80	24	24	14.5	14.5	1.5	2
TQFP	12x12x1.0 mm	100	24	24	14.5	14.5	1.5	2
TQFP	14x14x1.0 mm	64	24	20	16.5	16.5	1.9	2
TQFP	14x14x1.0 mm	80	24	20	16.5	16.5	1.9	2
TQFP	14x14x1.0 mm	100	24	20	16.5	16.5	1.9	2
TQFP	16x16x1.0 mm	144	32	24	19	19	1.7	2
TQFP	7x7x1.0 mm	32	16	12	9.6	9.6	1.85	2
TQFP	7x7x1.0 mm	48	16	12	9.6	9.6	1.85	2
TSOP	12x20 mm	48	32	16	12.5	20.6	2.1	2
TSOP	8x14 mm	32	24	12	8.6	14.5	1.8	2
TSOP	8x20 mm	28	32	16	8.6	20.6	2.1	2



Table 5: Microchip Technology Plastic Products, with Leads, Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity I	Index Quadrant		
		P C	W	P ₁	A ₀	B ₀	K ₀	_ <u> </u>
TSOP	8x20 mm	28	32	16	8.6	20.6	2.1	2
TSOP	8x20 mm	32	32	16	8.6	20.6	2.1	2
TSOP	8x20 mm	32	32	16	8.6	20.6	2.1	2
TSSOP	4.4 mm	8	12	8	6.75	3.4	1.3	2
TSSOP	4.4 mm	14	16	8	6.8	5.4	1.6	1
TSSOP	4.4 mm	14	16	8	6.8	5.4	1.6	1
TSSOP	4.4 mm	14	16	8	6.8	5.4	1.6	1
TSSOP	4.4 mm	16	16	8	6.8	5.4	1.6	1
TSSOP	4.4 mm	16	16	8	6.8	5.4	1.6	1
TSSOP	4.4 mm	16	16	8	6.8	5.4	1.6	1
TSSOP	4.4 mm	20	16	8	6.8	6.9	1.6	1
TSSOP	4.4 mm	20	16	8	6.8	6.9	1.6	1
VSOP		28	24	12	8.7	13.9	2.1	1-2



Table 6: Microchip Technology Plastic Products, With No Leads, Carrier Tape and Cavity Dimensions

	nty Dimensions	t al		rier nsions	Cavit	y Dimen	sions	änt
Package Type	Body Size	Terminal Count		m)		(mm)		Index Quadrant
		و ق	W	P ₁	A ₀	B ₀	K ₀	= m
DFN	2.5x2 mm	10	8	4	2.19	2.77	1.05	2
DFN	2x2x0.9 mm	6	8	4	2.3	2.3	1.00	2
DFN	2x2x0.9 mm	8	8	4	2.25	2.25	1.00	2
DFN	2x3x0.9 mm	6	8	4	2.3	3.2	1.00	2
DFN	2x3x0.9 mm	6	8	4	2.25	3.35	1.05	2
DFN	2x3x0.9 mm	6	12	8	2.2	3.2	1.1	2
DFN	2x3x0.9 mm	8	8	4	2.3	3.2	1.00	2
DFN	2x3x0.9 mm	8	8	4	2.25	3.35	1.05	2
DFN	2x3x0.9 mm	8	12	8	2.2	3.2	1.1	2
DFN	2x3x0.9 mm	8	12	4	2.3	3.3	1.1	2
DFN	3x3x0.9 mm	6	12	8	3.3	3.3	1.1	2
DFN	3x3x0.9 mm	6	12	8	3.3	3.3	1	2
DFN	3x3x0.9 mm	8	12	8	3.3	3.3	1.1	2
DFN	3x3x0.9 mm	8	12	8	3.3	3.3	1	2
DFN	3x3x0.9 mm	10	12	8	3.3	3.3	1.1	2
DFN	3x3x0.9 mm	10	12	8	3.3	3.3	1	2
DFN	4x4x09 mm	8	12	8	4.35	4.35	1.1	2
DFN	4x4x09 mm	16	12	8	4.35	4.35	1.1	2
DFN	4x4x09 mm	20	12	8	4.35	4.35	1.1	2
DFN	4x4x09 mm	24	12	8	4.35	4.35	1.1	2
DFN	4x4x09 mm	28	12	8	4.35	4.35	1.1	2
DFN-S	4x4x0.9 mm	8	12	8	4.35	4.35	1.1	2
DFN-S	5x6x0.9 mm	8	12	8	5.3	6.3	1.2	2
DFN-S	5x6x0.9 mm	8	16	12	5.3	6.3	1.3	2
DQFN	11x11 mm	132	24	16	11.4	11.4	1.2	2
QFN	3x3x0.9 mm	16	12	8	3.3	3.3	1.1	2
QFN	3x3x0.9 mm	16	12	8	3.3	3.3	1	2
QFN	4x4x0.9 mm	8	12	8	4.35	4.35	1.1	2



Table 6: Microchip Technology Plastic Products, With No Leads, Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dime	rier nsions m)	Cavit	y Dimen (mm)	sions	Index Quadrant
		P 0	W	P ₁	A ₀	B ₀	K ₀	- g
QFN	4x4x0.9 mm	8	12	8	4.35	4.35	1.1	2
QFN	4x4x0.9 mm	12	12	8	4.35	4.35	1.1	1
QFN	4x4x0.9 mm	16	12	8	4.35	4.35	1.1	2
QFN	4x4x0.9 mm	16	12	8	4.35	4.35	1.1	2
QFN	4x4x0.9 mm	20	12	8	4.35	4.35	1.1	2
QFN	4x4x0.9 mm	20	12	8	4.35	4.35	1.1	2
QFN	4x4x0.9 mm	24	12	8	4.35	4.35	1.1	2
QFN	4x4x0.9 mm	24	12	8	4.35	4.35	1.1	2
QFN	4x4x0.9 mm	28	12	8	4.35	4.35	1.1	2
QFN	4x4x0.9 mm	28	12	8	4.35	4.35	1.1	2
QFN	5x5x0.9 mm	20	12	8	5.25	5.25	1.1	2
QFN	5x5x0.9 mm	28	12	8	5.25	5.25	1.1	2
QFN	5x5x0.9 mm	40	12	8	5.25	5.25	1.1	2
QFN	6x6x0.9 mm	28	16	12	6.3	6.3	1.1	2
QFN	6x6x0.9 mm	28	16	12	6.3	6.3	1.1	2
QFN	6x6x0.9 mm	28	16	12	6.3	6.3	1.1	2
QFN	6x6x0.9 mm	40	16	12	6.3	6.3	1.1	2
QFN	7x7x0.9 mm	44	16	12	7.25	7.25	1.1	2
QFN	7x7x0.9 mm	48	16	12	7.25	7.25	1.1	2
QFN	7x7x0.9 mm	56	16	12	7.25	7.25	1.1	2
QFN	8x8x0.9 mm	40	16	12	8.3	8.3	1.1	2
QFN	8x8x0.9 mm	40	16	12	8.3	8.3	1.1	2
QFN	8x8x0.9 mm	44	16	12	8.3	8.3	1.1	2
QFN	8x8x0.9 mm	44	16	12	8.3	8.3	1.1	2
QFN	9x9x0.9 mm	64	16	12	9.3	9.3	1.1	2
TDFN	2x3x0.8 mm	6	8	4	2.30	3.2	1.0	2
TDFN	2x3x0.8 mm	6	8	4	2.25	3.35	1.05	2
TDFN	2x3x0.8 mm	6	12	8	2.2	3.2	1.1	2



Table 6: Microchip Technology Plastic Products, With No Leads, Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity Dimensions (mm)			Index Quadrant
		Te	W	P ₁	A ₀	B ₀	K ₀	_ §
TDFN	2x3x0.8 mm	8	8	4	2.30	3.2	1.0	2
TDFN	2x3x0.8 mm	8	8	4	2.25	3.35	1.05	2
TDFN	2x3x0.8 mm	8	12	8	2.2	3.2	1.1	2
TDFN	3x3x0.8 mm	10	12	8	3.3	3.3	1.1	2
TDFN	3x3x0.8 mm	10	12	8	3.3	3.3	1	2
TDFN-S	5x6x0.8 mm	8	12	8	5.3	6.3	1.2	2
TDFN-S	5x6x0.8 mm	8	16	12	5.3	6.3	1.3	2
UDFN	2x3x0.5 mm	8	12	4	2.3	3.3	8.0	2
UDFN	2x3x0.5 mm	8	8	4	2.3	3.2	1.0	2
UDFN	3x3x0.5 mm	10	12	8	3.4	3.4	0.55	2
UDFN	3x3x0.5 mm	10	12	8	3.3	3.3	8.0	2
UQFN	3x1.6x0.55 mm	6	12	8	1.95	3.5	0.75	2
UQFN	3x3x0.5 mm	10	12	8	3.4	3.4	0.55	2
UQFN	3x3x0.5 mm	16	12	8	3.4	3.4	0.55	2
UQFN	3x3x0.5 mm	20	12	8	3.4	3.4	0.55	2
UQFN	4x4x0.5 mm	16	12	8	4.25	4.25	0.9	2
UQFN	4x4x0.5 mm	20	12	8	4.25	4.25	0.9	2
UQFN	4x4x0.5 mm	28	12	8	4.25	4.25	0.9	2
UQFN	5x5x0.5 mm	40	12	8	5.3	5.3	0.75	2
UQFN	6x6x0.5 mm	48	16	12	6.3	6.3	0.9	2
UQFN	6x6x0.5 mm	48	16	12	6.3	6.3	8.0	2
VDFN	2.5x2 mm	10	8	4	2.19	2.77	1.05	2
VDFN	3x4.5 mm	14	12	8	3.35	4.85	1.2	1
VQFN	6x6x0.9 mm	32	16	12	6.3	6.3	1.1	2
VQFN	10x10x1.0 mm	72	24	12	10.4	10.4	1.4	1
WSON	5x6x0.8 mm	8	16	8	5.6	6.6	1.5	2
X2QFN	2.5x2.5x0.4 mm	16	8	4	2.74	2.74	0.69	2
X2SON	2X2X0.4 mm	8	8	4	2.24	2.24	0.75	2



Table 6: Microchip Technology Plastic Products, With No Leads, Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	rminal	Carrier Dimensions (mm)		Cavit	ndex ıadrant		
		Te O	W	P ₁	A ₀	B ₀	K ₀	_ g
XSON	1.5x1.5x0.45 mm	6	8	4	1.65	1.65	0.71	2
XSON	2X2X0.45 mm	8	8	4	2.24	2.24	0.75	2



Table 7: Microchip Technology Grid Array Products Carrier Tape and Cavity Dimensions

Package Type	Body Size	Carrier Dimensions (mm)			Cavit	y Dimen (mm)	sions	Index Quadrant
		<u>P</u>	W	P ₁	A ₀	B ₀	K ₀	_ g
TBGA	10x13 mm	80	24	16	10.6	13.6	1.90	1
TFBGA	10x10x1.0 mm	121	24	12	10.30	10.30	1.50	1
TFBGA	10x10 mm	169	24	12	10.4	10.4	1.4	1
TFBGA	10x10 mm	169	24	12	10.4	10.4	1.34	1
TFBGA	10x10 mm	169	24	12	10.3	10.3	2.2	1
TFBGA	12x12x1.2 mm	176	24	16	12.60	12.60	1.90	1
TFBGA	6x6 mm	84	12	8	6.3	6.3	1.3	1
TFBGA	6x8x1.0 mm	48	16	12	6.5	8.5	2.1	1
TFBGA	8x10x1.0 mm	48						1
TFBGA	8x10x1.2 mm	48	24	12	8.2	10.4	1.7	1
TFBGA	9x9x1.2 mm	84	16	12	9.25	9.25	2.1	1
VFBGA	6x8x0.8 mm	44	16	12	6.5	8.5	2.1	1
VFBGA	6x8x0.8 mm	56	16	12	6.5	8.5	2.1	1
WFBGA	4x4x0.8 mm	44	12	8	4.35	4.35	1.1	1
WFBGA	4x4x0.8 mm	34	12	8	4.4	6.4	1.4	1
WFBGA	4x6x0.8 mm	48	12	8	4.4	6.4	1.4	1
WFBGA	5x6x0.8 mm	48	12	8	5.3	6.3	1.2	1
WFBGA	6x6x0.8 mm	64	16	12	6.3	6.3	0.9	1
WFBGA	8x8x08 mm	100	16	12	8.3	8.3	0.9	1
WFBGA	9x9x0.65 mm	144	16	12	9.6	9.9	0.9	1
WFBGA	10x10x0.8 mm	144	24	12	10.4	10.4	1.4	1
WLCSP	2.225x2.170x0.64	16	8	4	2.36	2.31	0.75	1
XFBGA	7x7x0.5 mm	144	16	12	7.25	7.25	0.75	1
XFLGA	4x6x0.6 mm	48	12	8	4.4	6.4	1.4	1
XFLGA	5x6x0.6 mm	48	12	8	5.3	6.3	1.2	1



Table 8: Microchip Technology Module Carrier Tape and Cavity Dimensions

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavi	ty Dimens (mm)	sions	Index uadrant
		Te O	W	P ₁	A ₀	B ₀	K ₀	_ ថ
RF Module	(MA)	12	44	24	18.2	28.35	2.5	1
RF Module	(MB/MC)	12	44	28	23.3	33.4	4.1	1
RN4020			32	16	11.9	19.9	2.7	1
RN171	26.67x17.78x3.18	49	44	24	18.20	27.10	3.6	1

Table 9: SMSC Automotive (AIS) Products Carrier Tape and Cavity Dimensions

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavit	y Dimens (mm)	ions	Index Quadrant
		<u> </u>	W	P ₁	A ₀	B ₀	K ₀	_ <u> </u>
CABGA	12x12 mm	196	24	24	12.5	12.5	1.8	1
LQFP	10x10x1.4 mm	44	24	16	12.35	12.35	2.2	1
LQFP	14x14x1.4 mm	100	32	24	16.8	16.8	2.1	1
MQFP	14x20x2.7 mm	128	44	24	18.9	24.9	3.9	1
SiP	12.42x8.92x1.98 mm	45	24	12	9.3	12.75	2.3	2
SOIC	150 mils	8	12	8	6.4	5.2	2.1	1
SOIC	600 mils	28	32	16	10.9	18.5	3.2	1
TQFP	10x10x1.0 mm	44	24	16	12.45	12.45	1.6	1
TQFP	10x10x1.0 mm	64	24	16	12.45	12.45	1.6	1
TQFP	14x14x1.0 mm	128	24	20	16.5	16.5	1.55	1
VQFN	4x4x0.9 mm	16	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	20	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	24	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	28	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	32	12	8	4.35	4.35	1.1	1
VQFN	5x5x0.9 mm	28	12	8	5.25	5.25	1.1	1
VQFN	5x5x0.9 mm	32	12	8	5.25	5.25	1.1	1
VQFN	6x6x0.9 mm	36	16	12	6.3	6.3	1.1	1
VQFN	6x6x0.9 mm	40	16	12	6.3	6.3	1.1	1



Table 9: SMSC Automotive (AIS) Products Carrier Tape and Cavity Dimensions

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity Dimensions (mm)			Index Quadrant
		Te Te	W	P ₁	A ₀	B ₀	K ₀	_ g
VQFN	7x7x0.9 mm	48	16	12	7.25	7.25	1.1	1
VQFN	7x7x0.9 mm	56	16	12	7.25	7.25	1.1	1
VQFN	8x8x0.9 mm	56	16	12	8.30	8.30	1.4	1
VQFN	9x9x0.9 mm	64	16	12	9.3	9.3	1.1	1
VQFN	10x10x0.9 mm	72	24	12	10.4	10.4	1.4	1



Table 10: SMSC Commercial Products Carrier Tape and Cavity Dimensions

Package Type	Body Size	Terminal	Dimer	rier nsions im)	Cavit	y Dimen (mm)	sions	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
		P O	W	P ₁	A ₀	B ₀	K ₀	= g
DFN	3x3x0.9 mm	16	12	8	3.3	3.3	1.1	1
LFBGA	11x11x1.4 mm	169	24	16	11.3	11.3	1.7	1
LFBGA	11x11x1.4 mm	169	24	16	11.4	11.4	2	1
LFBGA	11x11x1.4 mm	169	24	16	11.35	11.35	2.1	1
LFBGA	13x13x1.3 mm	225	24	16	13.3	13.3	2.25	1
LFBGA	27x27x1.6 mm	324	44	32	27.5	27.5	3.6	1
MSOP	3x3x1.0 mm	8	12	8	5.3	3.4	1.4	1
MSOP	3x3x1.0 mm	10	12	8	5.3	3.4	1.4	1
PLCC	11.5x11.5x4.3 mm	28	24	16	13	13	4.9	1-2
QFN	1.8x1.3x0.55 mm	10	8	4	1.49	1.99	0.75	1
QFN	5x5x0.9 mm	16	12	8	5.25	5.25	1.1	1
QFN	5x5x0.9 mm	24	12	8	5.25	5.25	1.1	1
QFN	6x6x0.9 mm	36	16	12	6.3	6.3	1.1	1
QFN	6x6x0.9 mm	40	16	12	6.3	6.3	1.1	1
QFN	6x6x0.9 mm	40	16	12	6.3	6.3	1.1	1
QFN	7x7x0.9 mm	48	16	12	7.25	7.25	1.1	1
QFN	7x7x0.9 mm	56	16	12	7.25	7.25	1.1	1
QFN	8x8x0.9 mm	56	16	12	8.3	8.3	1.4	1
QFN	9x9x0.9 mm	64	16	12	9.3	9.3	1.1	1
QFP	14x20 mm	100	44	32	19	25	3.9	1
QSOP	.150 ln	24	16	8	6.5	9.5	2.3	1
QSOP	.150 In	28	16	8	6.5	10.3	2.3	1
SOIC	.150 ln	8	12	8	6.4	5.2	2.1	1
SOIC	.150 ln	14	16	8	6.5	9.5	2.1	1
SOIC	.150 In	16	12	8	6.4	5.2	2.1	1
SQFN	12x12x0.9 mm	100	24	16	12.4	12.4	1.1	1
TDFN	2x3x0.75 mm	8	12	8	2.2	3.2	1.1	2
TFBGA	7x7x1.0 mm	144	16	12	7.3	7.3	2.1	1
TQFP	14x14x1.0 mm	128	24	20	16.5	16.5	1.55	2
	•							



Table 10: SMSC Commercial Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavit	y Dimen (mm)	sions	2 2 1 1 1 1 1 1 1
		P P P	W	P ₁	A ₀	B ₀	K ₀	ੋ ਰ <u>ੋ</u>
TSOT	2.9x1.6 mm	5	8	4	3.23	3.17	1.37	2
TSOT	2.9x1.6 mm	6	8	4	3.23	3.17	1.37	2
UFBGA	3x3x0.6 mm	25	12	8	3.3	3.3	1.1	1
VFBGA	3x3x0.6 mm	25	12	8	3.3	3.3	1.1	1
VFBGA	4x4x0.8 mm	40	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	24	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	28	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	32	12	8	4.35	4.35	1.1	1
VQFN	6x6x0.9 mm	36	16	12	6.3	6.3	1.1	1
VQFN	6x6x0.9 mm	40	16	12	6.3	6.3	1.1	1
VQFN	7x7x0.9 mm	56	16	12	7.25	7.25	1.1	1
VQFN	7x7x0.9 mm	48	16	12	7.25	7.25	1.1	1
VQFN	8x8x0.9 mm	56	16	12	8.3	8.3	1.4	1
VQFN	8x8x0.9 mm	64	16	12	8.3	8.3	1.4	1
VQFN	9x9x0.9 mm	64	16	12	9.3	9.3	1.1	1
VQFN	10x10x0.9 mm	72	24	12	10.4	10.4	1.4	1
VQFN	12x12x0.9 mm	100	24	16	12.4	12.4	1.1	1
WFBGA	11x11x0.8 mm	169	24	16	11.4	11.4	1.2	1
WLCSP	2x2x0.62 mm	25	8	4	2.18	2.18	0.81	1
XFBGA	8x8x0.5 mm	169	16	12	8.3	8.3	0.9	1



Table 11: Supertex Products Carrier Tape and Cavity Dimensions

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavit	y Dimen (mm)	sions	Index Quadrant
		Te	W	P ₁	A ₀	B ₀	K ₀	_ _ _
CERQUAD	.650x.650 inches	44	32	24	18	18	4.9	1-2
DPAK (TO-252)		3	16	12	10.3	6.9	2.6	4
DPAK (TO-252)		5	16	12	10.3	6.9	2.6	4
FPBGA	5.7x5 mm	25	12	8	6.25	5.25	1.4	1
FPBGA	6x5.35 mm	26	16	8	5.5	6.5	1.2	2
LQFP	7x7x1.4 mm	32	16	12	9.8	9.8	2.0	1
LQFP	7x7x1.4 mm	48	16	12	9.8	9.8	2.0	1
MSOP	3x3 mm	8	12	8	5.3	3.4	1.4	1
MSOP	3x3 mm	8	12	8	5.3	3.4	1.4	1
MSOP	3x3 mm	10	12	8	5.3	3.4	1.4	1
MSOP	3x3 mm	10	12	8	5.3	3.4	1.4	1
PLCC		44	32	24	18	18	4.9	1-2
PLCC		44	32	24	18	18	4.1	1-2
PLCC	11.5x11.5x4.3 mm	28	24	16	13	13	4.9	1-2
PLCC	11.5x11.5x4.3 mm	28	24	16	13	13	4.9	1-2
PQFP (FP=3.9 mm)	10x10x2 mm	44	24	24	15.35	15.35	2.7	1
QFN	4x4x0.9 mm	16	12	8	4.3	4.3	1.25	1
QFN	4x4x0.9 mm	16	12	8	4.35	4.35	1.1	1
QFN	4x4x0.9 mm	16	12	8	4.35	4.35	1.1	1
QFN	4x4x0.9 mm	16	12	8	4.25	4.25	1.13	1
QSOP	7.5mm (.300 inches)	44	32	12	10.9	18.3	3	1
SOIC	.150 inches	8	12	8	6.4	5.2	2.1	1
SOIC	.150 inches	8	12	8	6.4	5.2	2.1	1
SOIC	.150 inches	8	12	8	6.5	5.2	2.1	1
SOIC	.150 inches	8	12	8	6.5	5.4	2	1
SOIC	.150 inches	8	12	8	6.5	5.3	2.1	1
SOIC	.150 inches	14	16	8	6.55	9.5	2.1	1
SOIC	.150 inches	14	16	8	6.5	9.5	2.1	1
SOIC	.150 inches	14	16	8	6.5	9.5	2.3	1



Table 11: Supertex Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavit	y Dimen (mm)	sions	Index Quadrant
		Te	W	P ₁	A ₀	B ₀	K ₀	ng I
SOIC	.150 inches	16	16	8	6.5	10.3	2.1	1
SOIC	.300 inches	16	8	8	6.55	10.38	2.1	1
SOIC	.300 inches	20	24	12	10.9	13.3	3	1
SOIC	.300 inches	20	24	12	10.9	13.3	3	1
SOIC	.300 inches	24	24	12	10.9	16	3	1
SOIC	.300 inches	24	24	12	10.8	15.9	3.2	1
SOIC	.300 inches	28	32	12	10.9	18.3	3	1
SOIC	.300 inches	16	16	12	10.9	10.7	3	1
SOIC	.300 inches	16	16	12	10.9	10.7	3.2	1
SOT-223		3	12	8	6.83	7.42	1.88	3
SOT-23		3	8	4	3.15	2.77	1.22	3
SOT-23		3	8	4	3.15	2.77	1.22	3
SOT-23		5	8	4	3.23	3.17	1.37	3
SOT-89		3	12	8	4.6	4.78	1.91	3
SOT-89		3	12	8	4.52	4.84	1.84	3
TO-92		3	S	ee Figure	e 13, Figu	re 14 and	d Figure 1	6
TSSOP	4.4 mm	24	16	8	6.9	8.4	1.7	1
VDFN	3x4x1.0 mm	10	12	8	3.3	4.3	1.2	1
VDFN	3x4x1.0 mm	10	12	8	3.3	4.3	1.2	1
VDFN	4x4x1.0 mm	8	12	8	4.35	4.35	1.1	1
VDFN	4x4x1.0 mm	8	12	8	4.35	4.35	1.1	1
VDFN	4x4x1.0 mm	8	12	8	4.3	4.3	1.1	1
VDFN	4x4x1.0 mm	12	12	8	4.3	4.3	1.25	1
VDFN	4x4x1.0 mm	12	12	8	4.35	4.35	1.1	1
VDFN	4x4x1.0 mm	12	12	8	4.35	4.35	1.1	1
VDFN	4x4x1.0 mm	12	12	8	4.25	4.25	1.13	1
VDFN	5x5x1.0 mm	8	12	8	5.25	5.25	1.1	1
VDFN	5x5x1.0 mm	8	12	8	5.25	5.25	1.1	1
VDFN	5x5x1.0 mm	8	12	8	5.3	5.3	1.25	1



Table 11: Supertex Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions im)	Cavit	y Dimen (mm)	sions	Index Quadrant
		Te	W	P ₁	A ₀	B ₀	K ₀	_ م
VDFN	5x5x1.0 mm	18	12	8	5.25	5.25	1.1	1
VDFN	5x5x1.0 mm	18	12	8	5.25	5.25	1.1	1
VDFN	5x5x1.0 mm	18	12	8	5.3	5.3	1.25	1
VQFN	3x3x0.9 mm	16	12	8	3.3	3.3	1.1	1
VQFN	3x3x0.9 mm	16	12	8	3.3	3.3	1	1
VQFN	3x3x0.9 mm	16	12	8	3.25	3.25	1.15	1
VQFN	3x3x0.9 mm	16	12	8	3.25	3.25	1.25	1
VQFN	4x4x0.9 mm	12	12	8	4.3	4.3	1.25	1
VQFN	4x4x0.9 mm	12	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	12	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	12	12	8	4.25	4.25	1.13	1
VQFN	4x4x0.9 mm	24	12	8	4.3	4.3	1.25	1
VQFN	4x4x0.9 mm	24	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	24	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	24	12	8	4.25	4.25	1.13	1
VQFN	4x4x1.0 mm	16	12	8	4.3	4.3	1.25	1
VQFN	4x4x1.0 mm	16	12	8	4.35	4.35	1.1	1
VQFN	4x4x1.0 mm	16	12	8	4.35	4.35	1.1	1
VQFN	4x4x1.0 mm	16	12	8	4.25	4.25	1.13	1
VQFN	5x5x1.0 mm	32	12	8	5.25	5.25	1.1	1
VQFN	5x5x1.0 mm	32	12	8	5.25	5.25	1.1	1
VQFN	5x5x1.0 mm	32	12	8	5.3	5.3	1.25	1
VQFN	6x6x1.0 mm	33	16	12	6.3	6.3	1.1	1
VQFN	6x6x1.0 mm	33	16	12	6.3	6.3	1.1	1
VQFN	6x6x1.0 mm	33	16	12	6.3	6.3	1	1
VQFN	6x6x1.0 mm	40	16	12	6.3	6.3	1.1	1
VQFN	6x6x1.0 mm	40	16	12	6.3	6.3	1.1	1
VQFN	6x6x1.0 mm	40	16	12	6.3	6.3	1	1
VQFN	7x7x1.0 mm	48	16	12	7.35	7.35	1.25	1



Table 11: Supertex Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rrier nsions nm)	Cavit	y Dimen (mm)	sions	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
		P C	W	P ₁	A ₀	B ₀	K ₀	_ <u> </u>
VQFN	7x7x1.0 mm	48	16	12	7.25	7.25	1.1	1
VQFN	8x8x1.0 mm	56	16	12	8.3	8.3	1.1	1
VQFN	8x8x1.0 mm	56	16	12	8.3	8.3	1.1	1
VQFN	8x8x1.0 mm	56	16	12	8.4	8.4	1.25	1
WDFN	3x3x0.8 mm	8	12	8	3.3	3.3	1.1	1
WDFN	3x3x0.8 mm	8	12	8	3.3	3.3	1	1
WDFN	3x3x0.8 mm	8	12	8	3.25	3.25	1.15	1
WDFN	3x3x0.8 mm	8	12	8	3.25	3.25	1.25	1
WDFN	3x3x0.8 mm	10	12	8	3.3	3.3	1.1	1
WDFN	3x3x0.8 mm	10	12	8	3.3	3.3	1	1
WDFN	4x4x0.8 mm	10	12	8	4.3	4.3	1.25	1
WDFN	4x4x0.8 mm	10	12	8	4.35	4.35	1.1	1
WDFN	4x4x0.8 mm	10	12	8	4.35	4.35	1.1	1
WDFN	4x4x0.8 mm	10	12	8	4.25	4.25	1.13	1
WFGA	3x3x0.85 mm	6	12	8	3.3	3.3	1.1	1
WFGA	3x3x0.85 mm	6	12	8	3.3	3.3	1	1
WQFN	3x3x0.8 mm	12	12	8	3.3	3.3	1.1	1
WQFN	3x3x0.8 mm	12	12	8	3.3	3.3	1	1
WQFN	3x3x0.8 mm	12	12	8	3.25	3.25	1.15	1
WQFN	3x3x0.8 mm	12	12	8	3.25	3.25	1.25	1
WQFN	3x3x0.8 mm	16	12	8	3.3	3.3	1.1	1
WQFN	3x3x0.8 mm	16	12	8	3.3	3.3	1	1
WQFN	3x3x0.8 mm	16	12	8	3.25	3.25	1.15	1
WQFN	3x3x0.8 mm	16	12	8	3.25	3.25	1.25	1
WQFN	4x5x0.9 mm	24	12	8	4.3	5.3	1.2	1
WQFN	5x5x0.8 mm	32	12	8	5.25	5.25	1.1	1
WQFN	5x5x0.8 mm	32	12	8	5.25	5.25	1.1	1
WQFN	5x5x0.8 mm	32	12	8	5.3	5.3	1.25	1
WQFN	5x5x0.8 mm	40	12	8	5.25	5.25	1.1	1



Table 11: Supertex Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Gount Asia Sing Appage		Dimer	rier nsions m)	Cavit	y Dimen (mm)	sions	Index Quadrant
		ĕ O	W	P ₁	A ₀	B ₀	K ₀	_ g
WQFN	5x5x0.8 mm	40	12	8	5.25	5.25	1.1	1
WQFN	5x5x0.8 mm	40	12	8	5.3	5.3	1.25	1
WQFN	6x6x0.8 mm	32	16	12	6.3	6.3	1.1	1
WQFN	6x6x0.8 mm	32	16	12	6.3	6.3	1.1	1
WQFN	6x6x0.8 mm	32	16	12	6.3	6.3	1	1
WQFN	7x7x0.8 mm	44	16	12	7.35	7.35	1.25	1
WQFN	7x7x0.8 mm	44	16	12	7.25	7.25	1.1	1



Table 12: ISSC Products Carrier Tape and Cavity Dimensions

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavit	ty Dimensions (mm)		Index Quadrant
		<u> </u>	W	P ₁	A ₀	B ₀	K ₀	_ ថ
VQFN	5x6.5x0.9 mm	48	16	8	5.3	6.8	1.2	1
VQFN	6x5x0.9 mm	42	12	8	5.3	6.3	1	2
VQFN	6x6x0.9 mm	40	16	8	6.3	6.3	1.1	1
VQFN	6x6x0.9 mm	48	16	8	6.3	6.3	1.1	1
VQFN	7x7x0.9 mm	48	16	12	7.3	7.3	1.2	1
VQFN	7x7x0.9 mm	56	16	12	7.3	7.3	1.2	1
VQFN	8x8x0.9 mm	56	16	12	8.3	8.3	1.2	2
VQFN	8x8x1.0 mm	56	16	12	8.3	8.3	1.2	2
VQFN	8x8x0.9 mm	68	16	12	8.3	8.3	1.2	2



Table 13: Micrel Products Carrier Tape and Cavity Dimensions

Package Type	Body Size	Terminal Count	Dimer	rier nsions im)	Cavit	Index Quadrant		
		<u> </u>	W	P ₁	A ₀	B ₀	K ₀	= a
B1QFN	12x12x3 mm	64	24	16	12.30	12.30	4.15	1
B1QFN	8x8x3 mm	52	16	12	8.3	8.3	3.4	1
B2QFN	10x10x4 mm	52	24	16	10.35	10.35	4.6	1
B2QFN	12x12x4 mm	64	24	16	13.30	12.30	4.15	1
DDPAK (TO-263)		3	24	16	10.60	16.50	4.90	2
DDPAK (TO-263)		3	24	16	10.6	16.5	4.9	2
DDPAK (TO-263)		3	24	16	10.6	16.50	4.90	2
DDPAK (TO-263)		5	24	16	10.6	16.5	4.9	2
DDPAK (TO-263)		5	24	16	10.60	16.50	4.9	2
DPAK (TO-252)		5	16	8	6.9	10.5	2.8	2
DPAK (TO-252)		2	N/A	N/A	N/A	N/A	N/A	2
DPAK (TO-252)		5	16	8	6.9	10.5	2.8	2
LFBGA	10x10x1.42 mm	100	24	12	10.4	10.4	1.6	1
LFBGA	9x9x1.38 mm	100	16	12	9.4	9.4	1.7	1
LLGA	5x7x1.45 mm	38	16	8	5.5	7.5	1.5	1
LQFP	14x14x1.4 mm	128	24	20	16.5	16.5	1.9	1
LQFP	14x14x1.4 mm	128	24	20	16.5	16.5	1.9	1
LQFP	10x10 mm	80	24	16	12.35	12.35	1.55	1
LQFP	10x10x1.4 mm	44	24	16	12.35	12.35	2.2	1
LQFP	10x10x1.4 mm	52	24	16	12.35	12.35	2.2	1
LQFP	10x10x1.4 mm	64	24	16	12.35	12.35	2.2	1
LQFP	10x10 mm	64	24	16	12.35	12.35	1.55	1
LQFP	7x7x1.4 mm	48	16	12	9.5	9.5	2	1
LQFP	07x07x1.6 mm	48	N/A	N/A	N/A	N/A	N/A	1
LQFP	07x07x1.6 mm	48	N/A	N/A	N/A	N/A	N/A	1
MSOP	3x3x1.0 mm	8	12	8	5.3	3.4	1.4	1
MSOP	3x3x1.0 mm	8	12	8	5.3	3.4	1.4	1
MSOP	3x3x1.0 mm	8	12	8	5.2	3.3	1.6	1
MSOP	3x3x1.0 mm	10	12	8	5.3	3.4	1.4	1
MSOP	3x3x1.0 mm	10	12	8	5.2	3.3	1.6	1
PLCC		44	N/A	N/A	N/A	N/A	N/A	1-2



Table 13: Micrel Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal	Dimer	rier nsions im)	Cavity Dimensions (mm)			Index Quadrant
		٥	W	P ₁	A ₀	B ₀	K ₀	= g
PLCC		32	24	16	N/A	N/A	N/A	1-2
PLCC		20	16	12	10.3	10.3	4.9	1-2
PLCC		28	24	16	13	13	4.9	1-2
PLCC		28	N/A	N/A	N/A	N/A	N/A	1-2
PLCC		28	N/A	N/A	N/A	N/A	N/A	1-2
PLCC		44	32	24	18	18	4.9	1-2
PQFP	14x20 mm	128	44	24	N/A	N/A	N/A	1
QFN	1x1x0.5 mm	4	8	2.0	1.16	1.16	0.63	1
QFN	4x4x0.8 mm	24	12	8	4.35	4.35	1.1	1
QSOP	.150 inches	16	12	8	6.5	5.2	2.1	1
QSOP	.150 inches	16	12	8	6.5	5.2	2.1	1
QSOP	.150 inches	20	12	8	N/A	N/A	N/A	1
SC70		3	8	4	2.4	2.4	1.2	3
SC70		4	8	4	N/A	N/A	N/A	N/A
SC70		5	8	4	2.25	2.4	1.22	2
SC70		6	8	4	2.25	2.4	1.22	2
SOIC	.150 inches	8	12	8	6.4	5.2	2.1	1
SOIC	.300 inches	28	32	16	10.75	18.6	3	1
SOIC	.150 inches	14	16	8	6.5	9.5	2.1	1
SOIC	.150 inches	16	16	8	6.5	10.3	2.1	1
SOIC	.300 inches	14	16	12	10.9	9.5	3	1
SOIC	.300 inches	16	16	12	10.9	10.7	3	1
SOIC	.300 inches	18	24	16	10.9	12.0	3.2	1
SOIC	.300 inches	20	24	12	10.9	13.3	3	1
SOIC	.300 inches	24	24	12	10.9	16	3	1
SOT-143		4	8	4	3.15	2.6	1.2	3
SOT-143		4	8	4	3.15	2.6	1.2	3
SOT-143		3	16	12	N/A	N/A	N/A	N/A
SOT-223		3	16	12	7.1	7.5	2.2	3
SOT-223		3	16	12	7.1	7.5	2.2	3
SOT-23		3	8	4	3.02	2.18	1.27	2



Table 13: Micrel Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavit	y Dimen (mm)	sions	Index Quadrant
		Te	W	P ₁	A ₀	B ₀	K ₀	_ g
SOT-23		3	8	4	3.15	2.77	1.22	2
SOT-23		5	8	4	3.2	3.1	1.4	2
SOT-23		5	8	4	3.23	3.17	1.37	2
SOT-23		5	8	4	3.23	3.17	1.37	2
SOT-23		6	8	4	3.2	3.1	1.4	2
SOT-23		6	8	4	3.23	3.17	1.37	2
SOT-23		6	8	4	3.23	3.17	1.37	2
SOT-23		8	8	4	3.2	3.1	1.4	2
SOT-23		8	8	4	3.23	3.17	1.37	2
SOT-23		8	8	4	3.23	3.17	1.37	2
SPAK		3	24	12	9.8	12	2.7	2
SPAK		5	24	12	9.8	12	2.7	2
SPAK		7	24	12	9.8	12	2.7	2
SSOP	5.3 mm	14	16	12	8.2	6.6	2.5	1
SSOP	5.3 mm	16	16	12	8.2	6.6	2.5	1
SSOP	5.3 mm	20	16	12	8.2	7.6	3.0	1
SSOP	5.3 mm	20	16	12	8.2	7.6	3.0	1
SSOP	5.3 mm	24	16	12	N/A	N/A	N/A	1
SSOP	5.3 mm	28	16	12	8.2	10.6	2.5	1
SSOP	5.3 mm	48	32	16	N/A	N/A	N/A	1
TDFN	2.5x2.0x1.15 mm	10	8	4	2.4	2.9	1.25	2
TDFN	3.5x3.0x1.15 mm	14	12	8	3.3	3.8	1.2	1
TDFN	1.2x1.2x0.4 mm	6	8	4	1.37	1.37	0.55	1
TDFN	1.2x1.6x0.4 mm	6	8	4	1.37	1.77	0.55	1
TQFN	4x4 mm	24	12	8	4.4	4.4	1	1
TQFN	5x5x0.85 mm	32	12	8	5.25	5.25	1.1	1
TQFN	7x7 mm	48	16	12	7.3	7.3	1.2	1
TQFN	8x8 mm	64	16	12	8.3	8.3	2.4	1
TQFP	07x07x1.2 mm	32	N/A	N/A	N/A	N/A	N/A	1
TQFP	07x07x1.2 mm	38	N/A	N/A	N/A	N/A	N/A	1
TQFP	10x10x.12 mm	64	N/A	N/A	N/A	N/A	N/A	1



Table 13: Micrel Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity Dimensions (mm)			Index Quadrant
		<u>Б</u>	W	P ₁	A ₀	B ₀	K ₀	- ag
TQFP	7x7 mm	48	16	12	9.35	9.35	1.2	1
TQFP	7x7x1.0 mm	32	16	12	N/A	N/A	N/A	1
TQFP	7x7x1.0 mm	48	16	12	9.35	9.35	12	1
TQFP	10x10x1.0 mm	64	24	16	N/A	N/A	N/A	1
TSOT		5	8	4	3.2	3.1	1.4	3
TSOT		5	8	4	3.23	3.17	1.37	3
TSOT		5	8	4	3.23	3.17	1.37	2
TSOT		6	8	4	3.2	3.1	1.4	2
TSOT		6	8	4	3.23	3.17	1.37	2
TSOT		6	8	4	3.23	3.17	1.37	2
TSSOP	4.4 mm	16	12	8	6.95	5.6	1.6	1
TSSOP	4.4 mm	20	16	8	6.8	6.9	1.6	1
TSSOP	4.4 mm	24	16	8	6.95	8.3	1.6	1
TSSOP	4.4 mm	8	12	8	N/A	N/A	N/A	1
TSSOP	4.4 mm	14	12	8	6.95	5.6	1.6	1
TSSOP	4.4 mm	28	16	8	6.8	10.2	1.6	1
UDFN	1.2x1.2x0.6 mm	4	8	4	1.35	1.35	0.76	2
UDFN	1.2x1.2x0.6 mm	6	8	4	1.35	1.35	0.76	2
UDFN	0.85x0.85x0.6 mm	4	N/A	N/A	N/A	N/A	N/A	1
UDFN	0.85x0.85 mm		8	2	0.97	0.87	0.73	1
UDFN	1.0x1.0 mm	4	8	2	1.16	1.16	0.63	1
UDFN	1.0x1.0 mm	4	8	4	1.15	1.15	0.65	1
UDFN	1x1x0.55 mm	4	8	4	1.16	1.16	0.63	1
UDFN	1.0x1.0 mm	6	8	2	1.16	1.16	0.63	1
UDFN	1.25x1.25 mm	4	8	4	N/A	N/A	N/A	1
UDFN	1.2x1.6x0.55 mm	8	8	4	1.38	1.78	0.78	1
UDFN	1.2x1.6x0.6 mm	8	8	4	1.38	1.78	0.78	1
UDFN	2x2x0.55 mm	6	8	4	2.30	2.30	1.0	1
UDFN	2x2x0.55 mm	8	8	4	2.30	2.30	1.0	1
UDFN	2x2x0.55 mm	10	8	4	2.30	2.30	0.75	1
UDFN	1.2x1.6x0.6 mm	8	8	4	1.38	1.78	0.78	1



Table 13: Micrel Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity Dimensions (mm)			Index Quadrant
		P 0	W	P ₁	A ₀	B ₀	K ₀	Qu
UDFN	1.2x1.6x0.6 mm	8	8	4	1.38	1.78	0.78	1
UDFN	1.6x1.6x0.6 mm	6	8	4	1.78	1.78	0.69	1
UDFN	1.6x2.0x0.6 mm		8	4	1.79	2.12	0.75	1
UDFN	2x2x0.6 mm	6	8	4	2.30	2.30	0.75	1
UDFN	2x2x0.6 mm	8	8	4	2.30	2.30	0.75	1
UDFN	2x2x0.6 mm	10	8	4	2.30	2.30	0.75	1
UDFN	2x2x0.6 mm	22	8	4	N/A	N/A	N/A	1
UDFN	2.5x2.5x0.6 mm	10	8	4	2.77	2.77	0.8	1
UDFN	2.5x2.5x0.6 mm	12	8	4	2.77	2.77	0.8	1
UDFN	3x3x0.6 mm		12	8	N/A	N/A	N/A	1
UDFN	1.2x1.2x0.55 mm	4	8	4	1.35	1.35	0.76	1
UDFN	1.2x1.2x0.55 mm	6	8	4	1.35	1.35	0.76	1
UDFN	3x3x0.6 mm		12	8	3.3	3.3	1.1	1
UQFN	2x2x0.6 mm	8	8	4	2.30	2.3	0.75	1
UQFN	1x1x0.6 mm	10	N/A	N/A	N/A	N/A	N/A	1
UQFN	2x2x0.6 mm	12	8	4	2.30	2.3	0.75	1
UQFN	2.5x2.5x0.6 mm	14	8	4	2.77	2.77	0.80	1
UQFN	2.0x2.5x0.6 mm	16	8	4	2.77	2.77	0.80	1
VDFN	2.0x2.5 mm	4	N/A	N/A	N/A	N/A	N/A	1
VDFN	2.0x2.5 mm	6	N/A	N/A	N/A	N/A	N/A	1
VDFN	2x2x0.6 mm	8	8	4	2.30	2.30	0.75	1
VDFN	3x4x0.9 mm	10	12	8	3.40	4.40	1.1	1
VDFN	2x2x0.9 mm	6	8	4	2.30	2.30	1.0	1
VDFN	2x2x0.9 mm	8	8	4	2.30	2.30	1.0	1
VDFN	2.5x2.5x0.9 mm	10	12	4	2.8	2.8	1.1	1
VDFN	2.5x2.5x0.9 mm	14	12	4	2.8	2.8	1.1	1
VDFN	3x3x0.9 mm	8	12	8	3.3	3.3	1.1	1
VDFN	3x3x0.9 mm	8	12	8	3.3	3.3	1.1	1
VDFN	3x3x0.9 mm	10	12	8	3.3	3.3	1.1	1
VDFN	3x3x0.9 mm	10	12	8	3.3	3.3	1.1	1
VDFN	3x3x0.9 mm	12	12	8	3.3	3.3	1.1	1



Table 13: Micrel Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity Dimensions (mm)			Index Quadrant
		<u> </u>	W	P ₁	A ₀	B ₀	K ₀	= p
VDFN	3x3x0.9 mm	12	12	8	3.3	3.3	1.1	1
VDFN	3x3x0.9 mm	16	12	8	3.3	3.3	1.1	1
VDFN	3x3x0.9 mm	16	12	8	3.3	3.3	1.1	1
VDFN	4x4x0.9 mm	8	12	8	4.35	4.35	1.1	1
VDFN	4x4x0.9 mm	8	12	8	N/A	N/A	N/A	1
VDFN	4x4x0.9 mm	12	12	8	4.35	4.35	1.1	1
VDFN	4x4x0.9 mm	12	12	8	4.35	4.35	1.1	1
VDFN	4x5x0.9 mm	20	12	8	4.30	5.30	1.1	1
VDFN	4x5x0.9 mm	20	12	8	4.37	5.64	1.88	1
VLGA	5.5x5.5x0.8 mm	76	12	8	N/A	N/A	N/A	1
VQFN	2x2x0.9 mm	10	N/A	N/A	N/A	N/A	N/A	1
VQFN	3.5x3.0x1 mm	14	N/A	N/A	N/A	N/A	N/A	1
VQFN	3.0x3.5x0.9 mm	16	N/A	N/A	N/A	N/A	N/A	1
VQFN	3x4x0.9 mm	24	12	8	3.40	4.40	1.1	1
VQFN	4x6x0.9 mm	28	12	8	4.40	6.40	1.4	1
VQFN	5x4x0.9 mm	28	N/A	N/A	N/A	N/A	N/A	1
VQFN	5x4x0.9 mm	28	N/A	N/A	N/A	N/A	N/A	1
VQFN	2x2x0.85 mm	6	8	4	2.30	2.30	1	1
VQFN	3x3x0.85 mm	16	12	8	3.3	3.3	1.1	1
VQFN	3x3x0.9 mm	12	12	8	3.3	3.3	1.1	1
VQFN	3x3x0.9 mm	12	12	8	3.3	3.3	1.1	1
VQFN	2.5x2.0 mm	10	8	4	2.40	2.90	1.25	1
VQFN	3.0x3.5 mm	14	12	8	3.25	3.95	1	1
VQFN	4x6 mm	28	12	8	4.4	6.4	1.4	1
VQFN	4x6 mm	28	12	8	4.4	6.40	1.4	1
VQFN	2.5x2.8x0.9 mm	17	8	4	2.8	3.25	1.1	1
VQFN	2.5x2.8x0.9 mm	17	8	4	N/A	N/A	N/A	1
VQFN	3x3x0.9 mm	16	12	8	3.3	3.3	1.1	1
VQFN	3x3x0.9 mm	16	12	8	3.3	3.3	1.1	1
VQFN	3x4x0.9 mm	20	12	8	3.4	4.4	1.1	1
VQFN	3x4x0.9 mm	20	12	8	3.4	4.4	1.1	1



Table 13: Micrel Products Carrier Tape and Cavity Dimensions (Continued)

Package Type	Body Size	Terminal Count	Dimer	rier nsions m)	Cavity Dimensions (mm)			Index Quadrant
		Te	W	P ₁	A ₀	B ₀	K ₀	ng I
VQFN	4x4x0.9 mm	16	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	16	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	24	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	24	12	8	4.25	4.25	1.1	1
VQFN	4x4x0.9 mm	28	12	8	4.35	4.35	1.1	1
VQFN	4x4x0.9 mm	28	12	8	N/A	N/A	N/A	1
VQFN	5x5x0.9 mm	32	12	8	5.25	5.25	1.1	1
VQFN	5x5x0.9 mm	32	12	8	5.25	5.25	1.1	1
VQFN	5x6x0.9 mm	28	12	8	5.3	6.3	1.2	1
VQFN	7x7x0.9 mm	44	16	12	7.25	7.25	1.1	1
VQFN	7x7x0.9 mm	44	16	12	7.25	7.25	1.1	1
VQFN	7x7x0.9 mm	48	16	12	7.25	7.25	1.1	1
VQFN	7x7x0.9 mm	48	16	12	7.25	7.25	1.1	1
VQFN	8x8x0.9 mm	64	16	12	N/A	N/A	N/A	1
WLCSP	1.2x0.8x0.63 mm	6	8	4	0.88	1.28	0.68	1
WLCSP	1.3x1.3x0.715 mm	9	8	4	1.38	1.38	0.7	1
WLCSP	1.74x1.64x0.59 mm	9	8	4	1.71	2.08	0.71	1
WLCSP	1.8x1.7x0.67 mm	16	8	4	1.8	1.95	0.75	2
WLCSP	1.85x1.85x0.61 mm	16	8	4	2.07	2.07	0.89	2
WLCSP	2.1x1.1 mm	8	N/A	N/A	N/A	N/A	N/A	1
WLCSP		6	N/A	N/A	N/A	N/A	N/A	1
WDFN	3x2x0.8 mm	14	8	4	3.29	2.31	1.1	2
WDFN	1.2x1.6x0.8 mm	4	8	4	1.42	1.8	0.91	1
WDFN	1.2x1.6x0.8 mm	4	8	4	1.47	1.73	0.65	1
WDFN	1.2x1.6x0.8 mm	4	8	4	N/A	N/A	N/A	1
WDFN	1.6x1.6x0.8 mm	6	8	4	1.9	1.9	1	1
WDFN	1.6x1.6x0.8 mm	6	8	4	1.91	1.98	0.91	1



WAFER LEVEL CHIPSCALE PACKAGES (WLCSP, CSP)

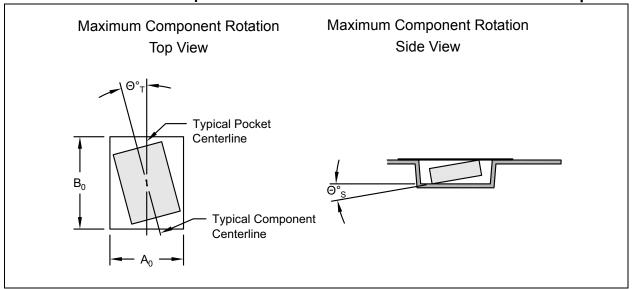
Please contact your Microchip sales representative or supplier for specific carrier tape information that is not listed in this document.

Table 14: Cover Tape Dimensions

Carrier Width	Width (mm)	Thickness (mm)
8 mm	5.3	0.062
12 mm	9.3	0.062
12 mm	9.2	0.05
12 mm	9.05	0.05
16 mm	13.05	0.05
16 mm	13.3	0.05
24 mm	21	0.05
32 mm	25.5	0.05
44 mm	37.5	0.05



FIGURE 5: Maximum Component Rotation for Punched and Embossed Carrier Tape



Tape Width (mm)	Maximum Rotation Θ° _T
8, 12	20
16~200	10

Tape Width (mm)	Maximum Rotation Θ° _S
8, 12	20
16~56	10
72~200	5

FIGURE 6: Maximum Lateral Movement for Punched and Embossed Carrier

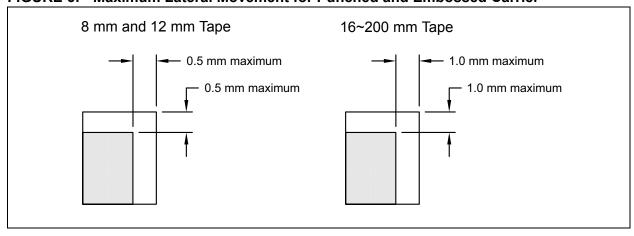




FIGURE 7: Bar Code Label Area for Punched and Embossed Carrier

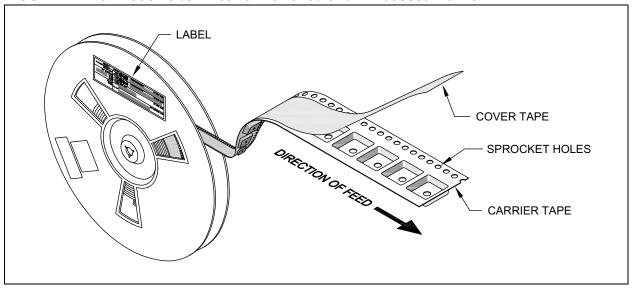


FIGURE 8: Bending Radius for Punched and Embossed Carrier

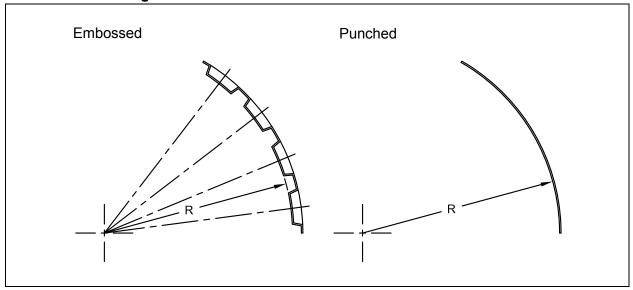
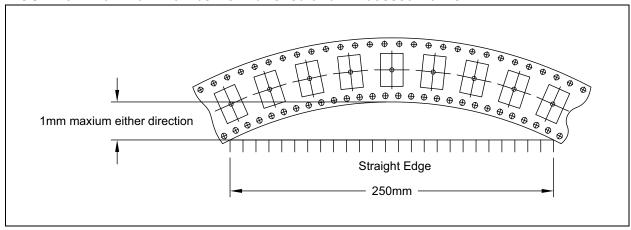




FIGURE 9: Maximum Camber for Punched and Embossed Carrier



To measure camber accurately, place the starting end of the carrier tape sample on the left end of the measurement fixture or straight edge. Moving to the right, measure the allowable camber at the highest point between where the left edge and the right edge of the carrier tape make contact with the measurement fixture or straight edge.

FIGURE 10: Measuring Camber for Punched and Embossed Carrier

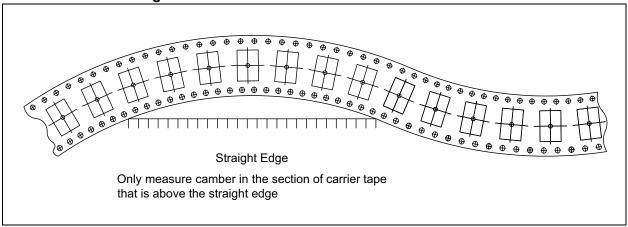




FIGURE 11: Ten Pitches Cumulative Sprocket Holes Measurement

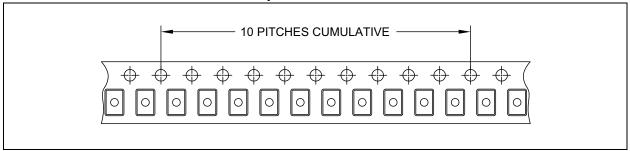
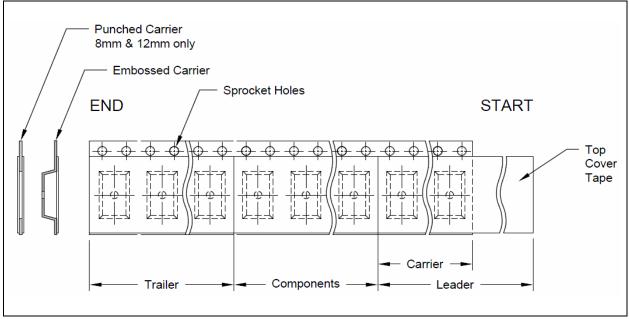


FIGURE 12: Tape Leader and Trailer Dimensions



- 1. There shall be a leader of 400 mm minimum of cover tape, which includes at least 100 mm of carrier tape with empty compartments and sealed by the cover tape. All of the leader may consist of the carrier tape with empty compartments sealed by cover tape.
- 2. There shall be a trailer of 160 mm minimum of empty carrier tape sealed with cover tape. The entire carrier tape must release from the reel hub as the last portion of the tape unwinds from the reel without damage to the carrier tape and the remaining components in the cavities.



FIGURE 13: Reel With a Drive Hole

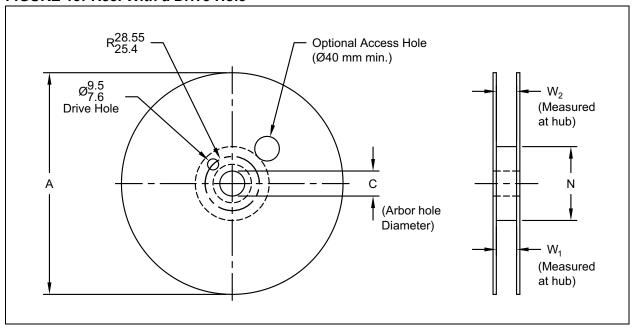


FIGURE 14: Reel Without a Drive Hole

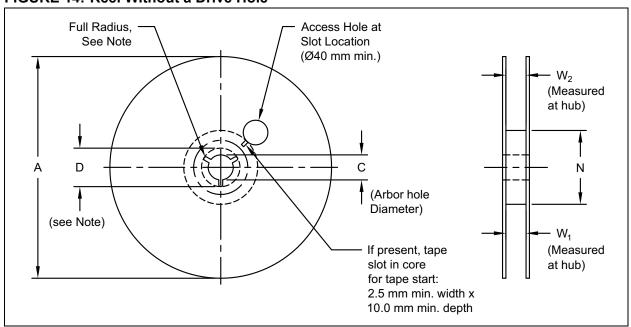




Table 15: Plastic Reel Dimensions:

Carrier Width	(A) Reel Diameter (mm) ±3.0 or as specified	(N) Hub Diameter (mm) ±1.5 or as specified	(W ₁) Reel Thickness (mm) +2.0 -0.0 or as specified	(W ₂) Total Thickness (mm) Max	(C) Center Hole Diameter (mm) ±0.2 or as specified
8 mm	330	60	8.4	14.4	13
8 mm	178±2.0	60.5±0.5	8.4 ^{+1.5}	14.4	13 ^{+0.5} _{-0.2}
8 mm	180 ⁺⁰ _{-1.5}	60 ⁺¹ ₋₀	9 ⁺¹ ₋₀	11.4±1.0	13
8 mm	177-179	59-61	8.5-9.5		12.8-13.5
12 mm	328-332	100-101	13.0-14.0	18.4	12.8-13.5
12 mm	328-332	100-102	12.4-14.4	18.4	12.8-13.5
12 mm	328-332	179.5 -183.5	12.4-13.4	18.2	12.8-13.5
12 mm	330+2.0	100±2.0	12.4 ⁺² ₋₀	18.4	13 ^{+0.5} _{-0.2}
16 mm	328-332	100-101	17.0-18.0	22.5	12.5-13.5
16 mm	328-332	100-102	16.4-18.4	22.4	12.8-13.5
16 mm	330±2.0	100±2.0	16.4 ⁺² ₋₀	22.4	13 ^{+0.5} _{-0.2}
24 mm	328-332	100-102	24.4-26.4	38.4	12.8-13.5
24 mm	330±2.0	100±2.0	24.4±2.0	30.4	13 ^{+0.5} _{-0.2}
32 mm	328-332	100-102	32.4-34.4	38.4	12.8-13.5
32 mm	330±2.0	100±2.0	32.4±2.0	38.4	13
44 mm	328-332	100-102	44.4-46.4	50.4	12.8-13.5
44 mm	330±2.0	100±2.0	44.4±2.0	50.4	13 ^{+0.5} _{-0.2}



FIGURE 15: TO-92 Carrier Tape Dimensions

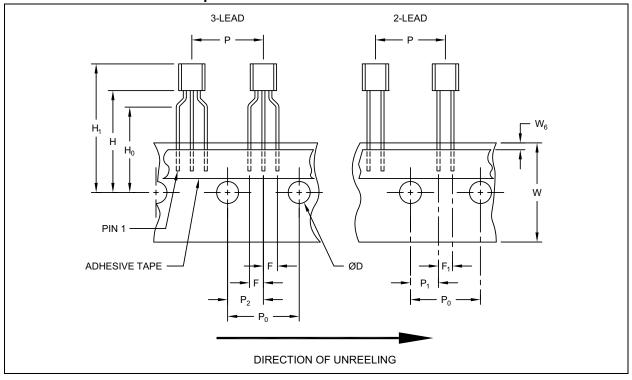


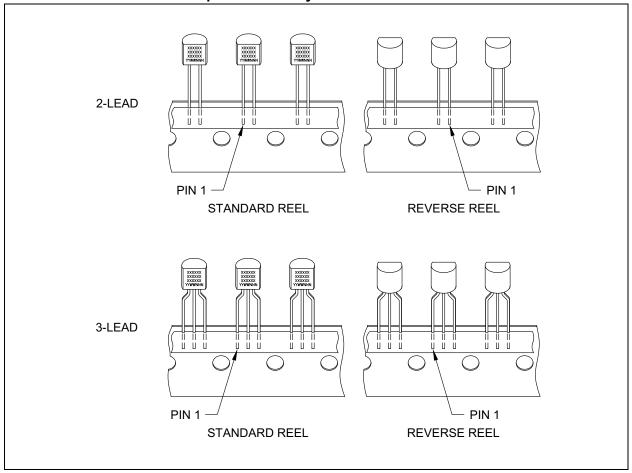
Table 16: TO-92 Carrier Tape Dimensions

Symbol	Description	Dimension (mm)
D	Sprocket Hole Diameter	4.0 ±0.2
Р	Device Pitch	12.7 ±0.1
P ₀	Feed Hole Pitch	12.7 ±0.1
P ₁	Ordinate to Adjacent lead (2-Lead TO-92)	5.07 ±0.7
P ₂	Ordinate to Center Lead (3-Lead TO-92)	6.35 ±0.7
F ₁	2 Lead TO-92 Spacing	2.54 ^{+0.6} _{-0.2}
F	3 Lead TO-92 Spacing	2.54 ^{+0.4} _{-0.1}
H ₀	Height to Seating Plane (Formed Leads)	15.5 MIN.
H ₁	Overall Height Above Abscissa	32.2 MAX.
Н	Height to Seating Plane (Straight Leads)	16-21
W	Carrier Tape Width	18
W ₆	Adhesive Tape Position	3 MAX.
-	Output Quantity Units	1000
-	Reel Diameter	355



Source: EIA-481

FIGURE 16: BGA and LGA Square Geometry





EIA STANDARD PACKAGE ORIENTATION

FIGURE 17: BGA and LGA Rectangular Geometry

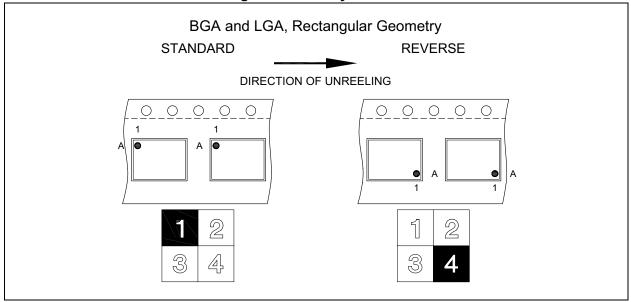


FIGURE 18: BGA and LGA Rectangular Geometry

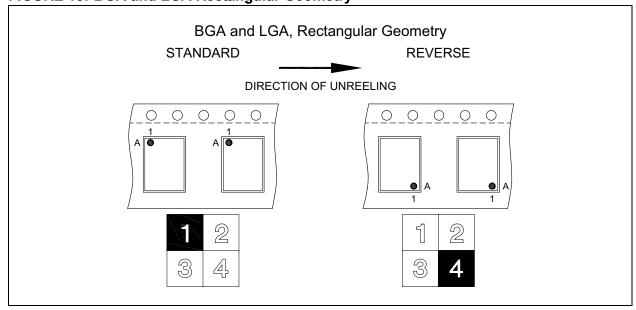




FIGURE 19: BGA and LGA Rectangular Geometry, Rotated

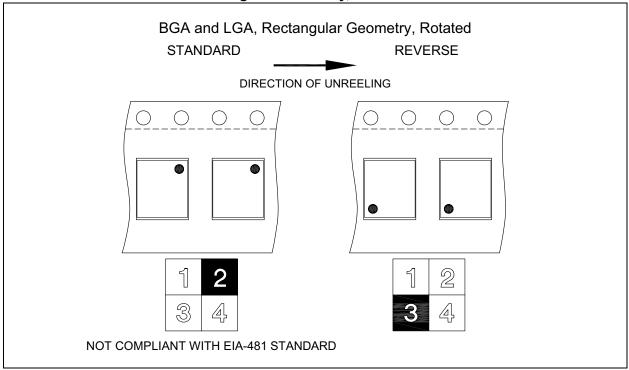


FIGURE 20: BGA and LGA Square Geometry

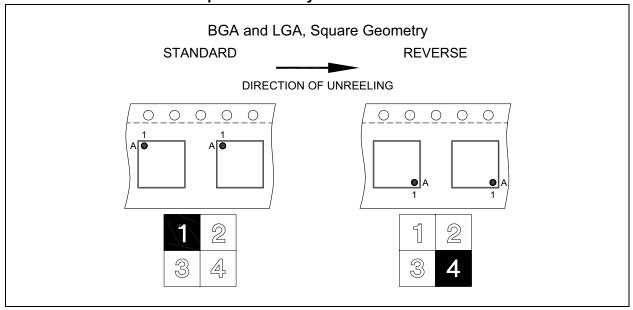




FIGURE 21: DFN, Rectangular Geometry

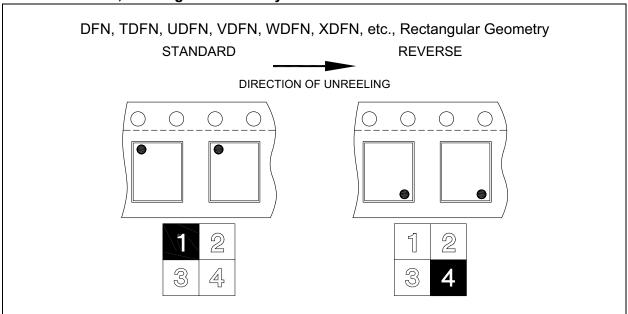


FIGURE 22: DFN, Rectangular Geometry, Rotated

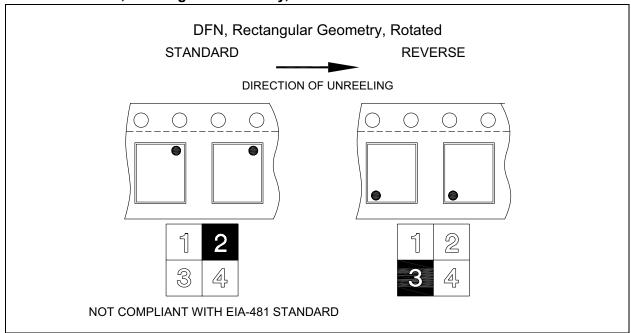




FIGURE 23: DFN, Rectangular Geometry

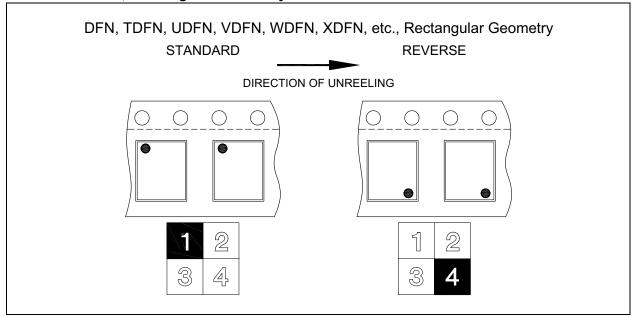


FIGURE 24: DFN Rectangular Geometry, Rotated

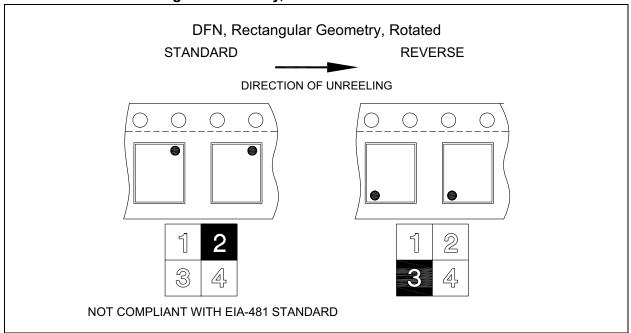




FIGURE 25: DFN Square Geometry

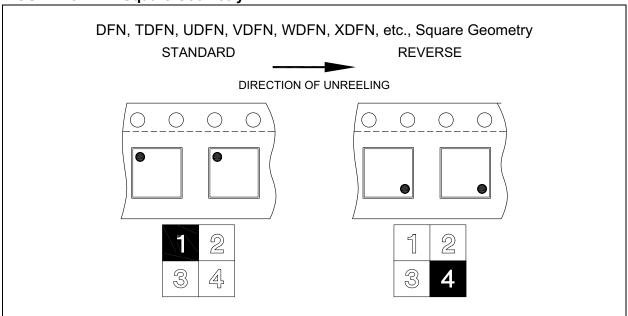


FIGURE 26: DFN Square Geometry, Rotated

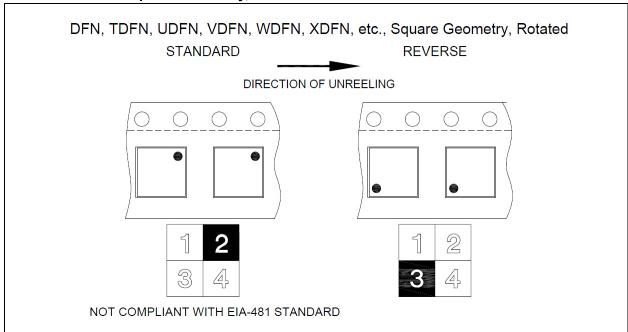




FIGURE 27: DDPAK or D²PAK (TO-263)

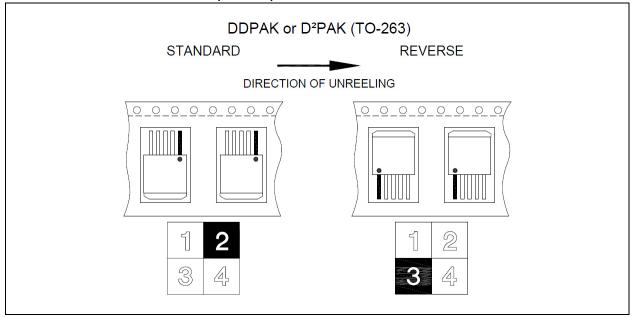
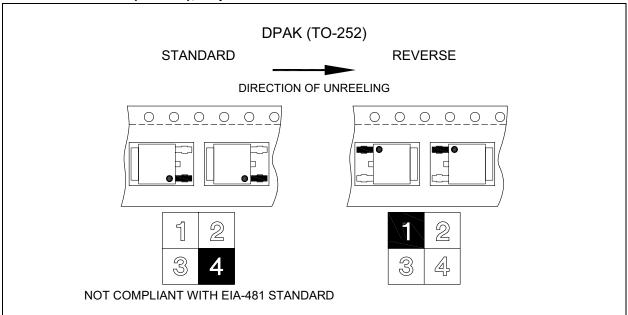


FIGURE 28: DPAK (TO-252), Supertex







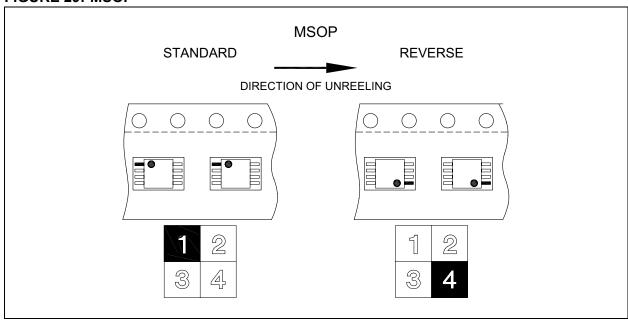


FIGURE 30: PLCC Rectangular Geometry

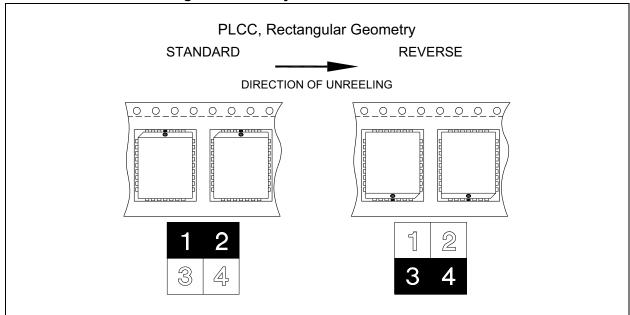




FIGURE 31: PLCC Square Geometry

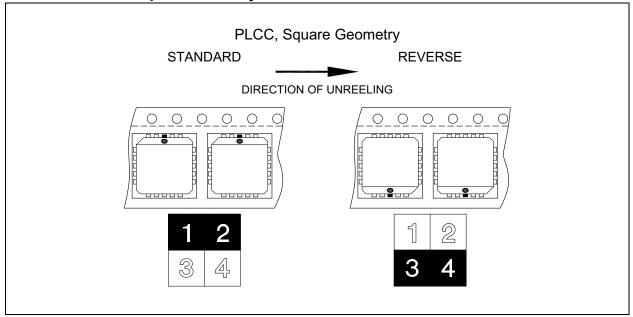


FIGURE 32: QFN Rectangular Geometry

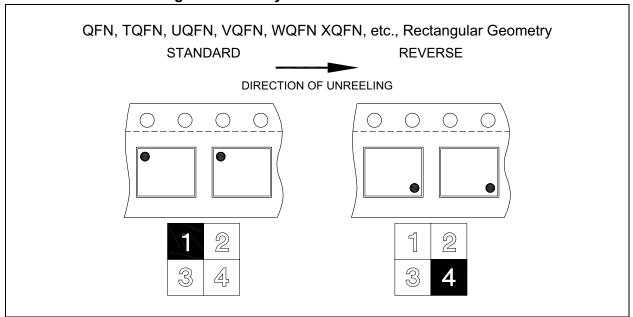




FIGURE 33: QFN Rectangular Geometry, Rotated

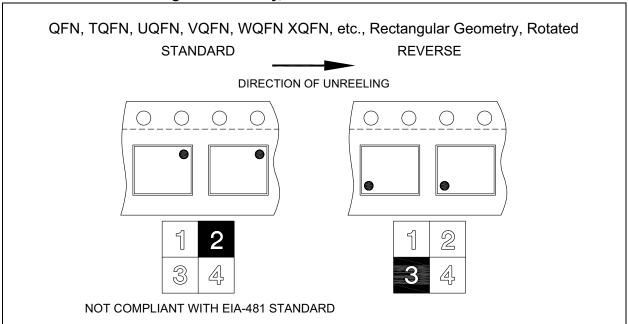


FIGURE 34: QFN Rectangular Geometry

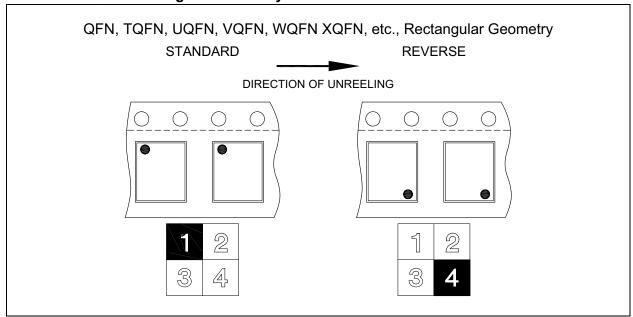




FIGURE 35: QFN Rectangular Geometry, Rotated

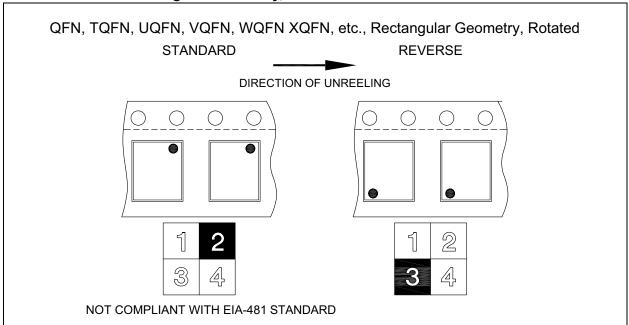


FIGURE 36: QFN Square Geometry

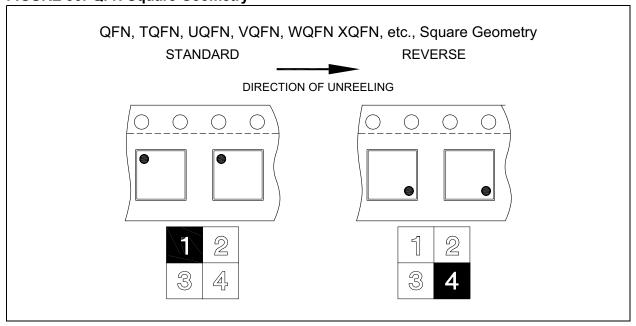




FIGURE 37: QFN Square Geometry, Rotated

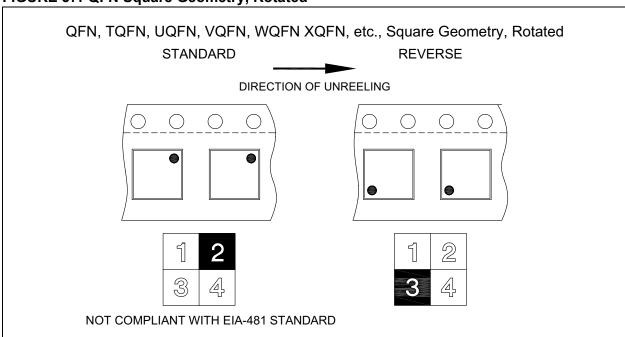


FIGURE 38: QFP, LQFP, MQFP, PQFP, and TQFP Rectangular Geometry

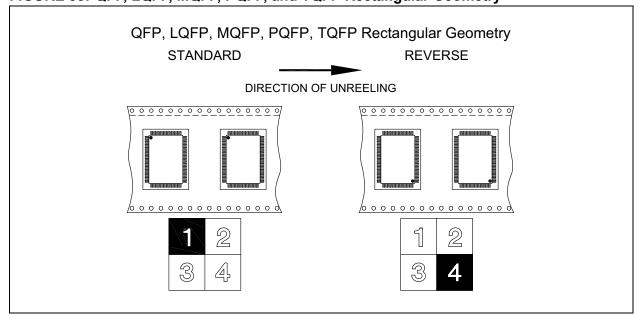




FIGURE 39: QFP, LQFP, MQFP, PQFP and TQFP Square Geometry

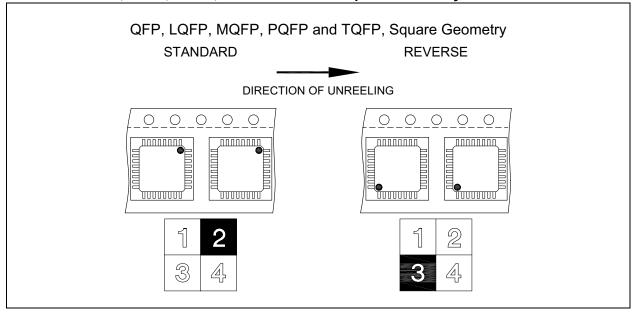


FIGURE 40: QFP, LQFP, MQFP, PQFP and TQFP Square Geometry, Rotated

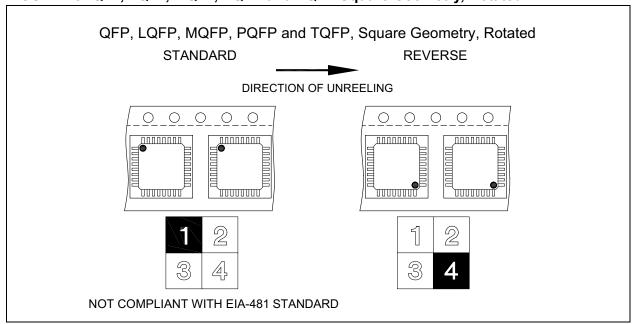




FIGURE 41: QSOP, SSOP and TSSOP

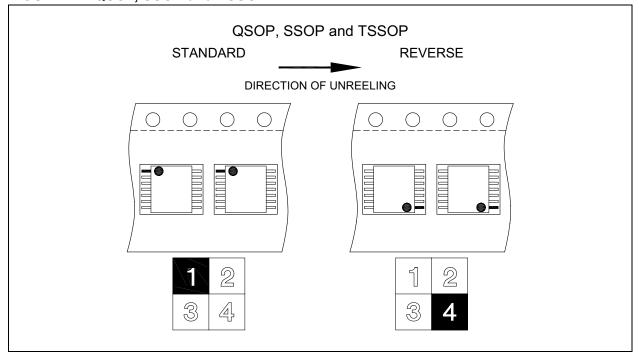


FIGURE 42: SC70 5-Lead

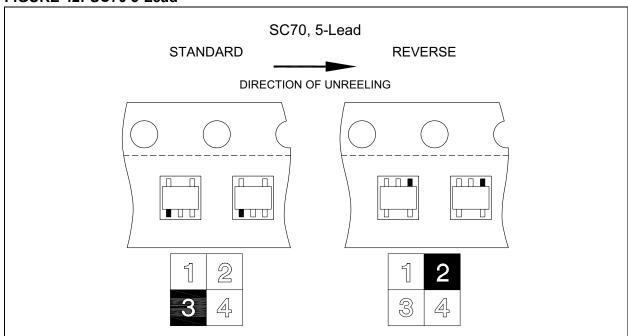




FIGURE 43: SC70 6 Lead

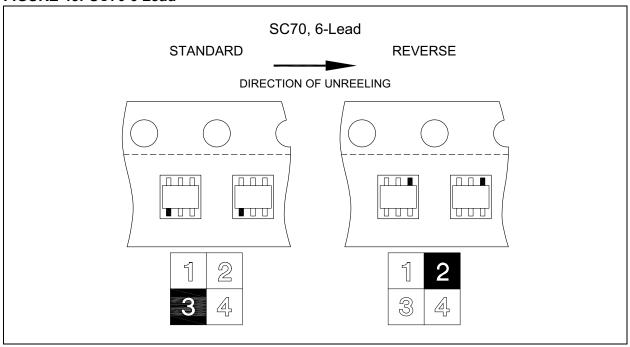


FIGURE 44: SiP (System in Package)

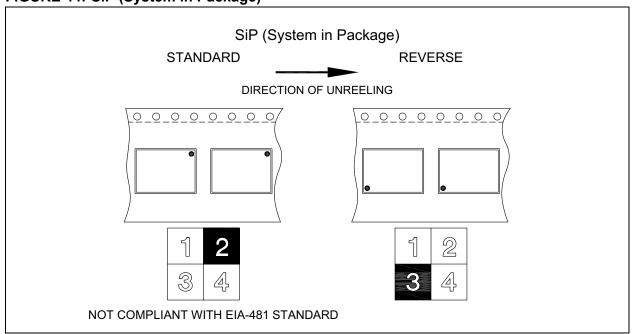




FIGURE 45: SOIC

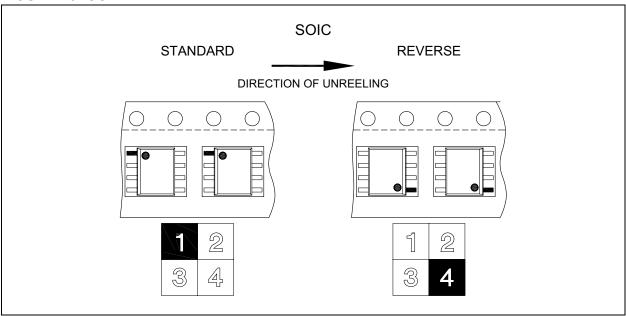


FIGURE 46: SOT-143

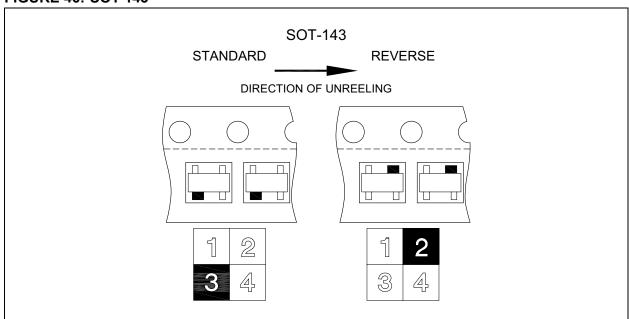




FIGURE 47: SOT-233

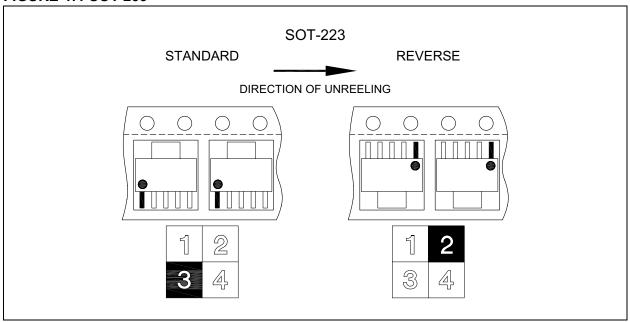


FIGURE 48: SOT-23 and TSOT, 3 Lead

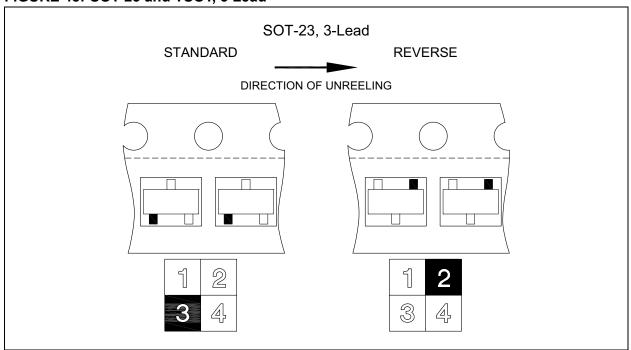




FIGURE 49: SOT-23 and TSOT, 5 Lead

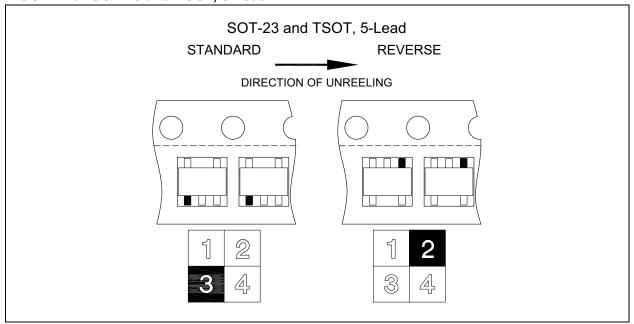


FIGURE 50: SOT-23 and TSOT, 6 Lead

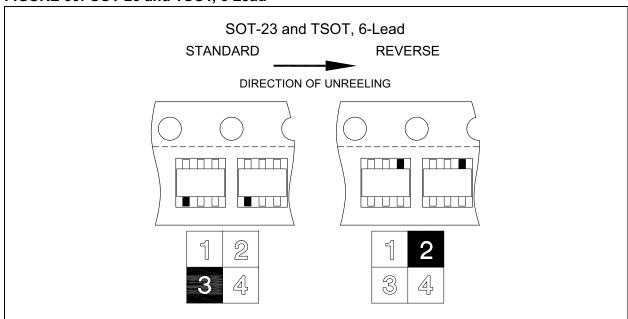




FIGURE 51: SOT-23 and TSOT, 8 Lead

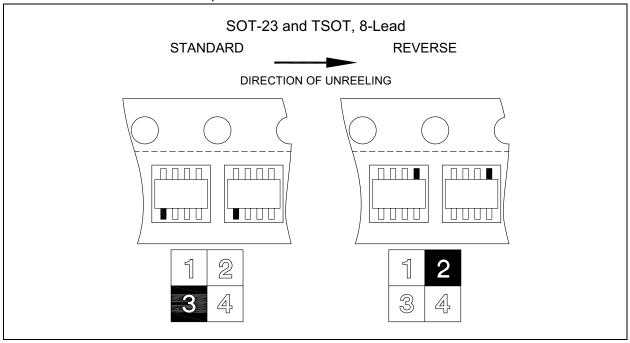


FIGURE 52: SOT-89

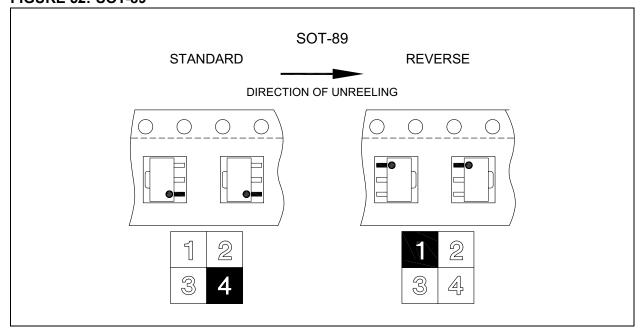




FIGURE 53: SOT-89, Rotated

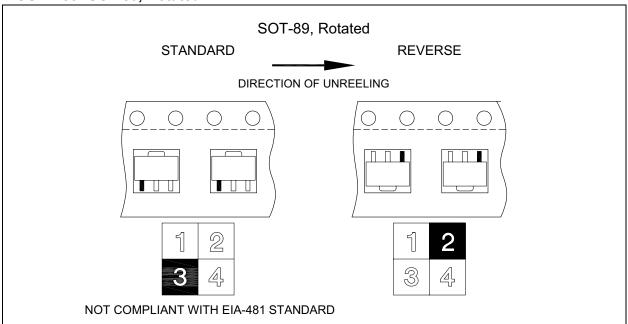


FIGURE 54: SPAK

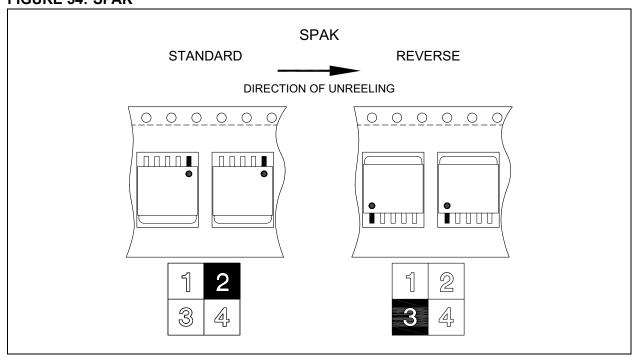
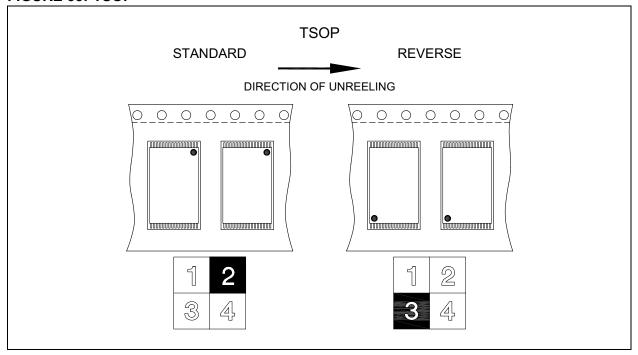




FIGURE 55: TSOP





NOTES:



APPENDIX A: REVISION HISTORY

Revision Q Document (August 2017)

Changes were made to the following tables:

Table 6: Microchip Technology Plastic Products, With No Leads, Carrier Tape and Cavity Dimensions

Table 9: SMSC Automotive (AIS) Products Carrier Tape and Cavity Dimensions

Table 11: Supertex Products Carrier Tape and Cavity Dimensions

Revision P Document (March 2017)

Changes were made to the following tables:

Table 9: SMSC Automotive (AIS) Products Carrier Tape and Cavity Dimensions

Table 11: Supertex Products Carrier Tape and Cavity Dimensions

Revision N Document (January 2017)

Changes were made to the following table:

Table 11: Supertex Products Carrier Tape and Cavity Dimensions

Revision M Document (December 2016)

Changes and additions were made to the following tables:

Table 7: Microchip Technology Grid Array Products Carrier Tape and Cavity Dimensions

Table 8: Microchip Technology Module Carrier Tape and Cavity Dimensions

Table 11: Supertex Products Carrier Tape and Cavity Dimensions

Revision L Document (October 2016)

TABLE 13: ISSC Products Carrier Tape and Cavity Dimensions was corrected to TABLE 13: Micrel Products Carrier Tape and Cavity Dimensions.

Revision K Document (September 2016)

Specification rewrite.

Revision J Document (March 2016)

Specification rewrite.

Revision H Document (November 2011)

Removed the section "Dimensions and Tolerances" that was Appendix A in the previous version.

Revision G Document (September 2010)

Included additional package style codes, so packages that are identical except for the associated package designators are listed separately; once by the Microchip designator, and again by the TelCom designator. For example, a 5-Lead SOT-23 package is listed twice in the Carrier Tape and Cavity Dimensions table – once as an OT package style code, and again as a CT package style code.

Revision F Document (February 2008)

The content and drawings in this document have been revised for this new version.



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Fax: 86-21-3326-8021

China - Shenyang
Tel: 86-24-2334-2829

Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen Tel: 86-755-8864-2200 Fax: 86-755-8203-1760

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China - Xian Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

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